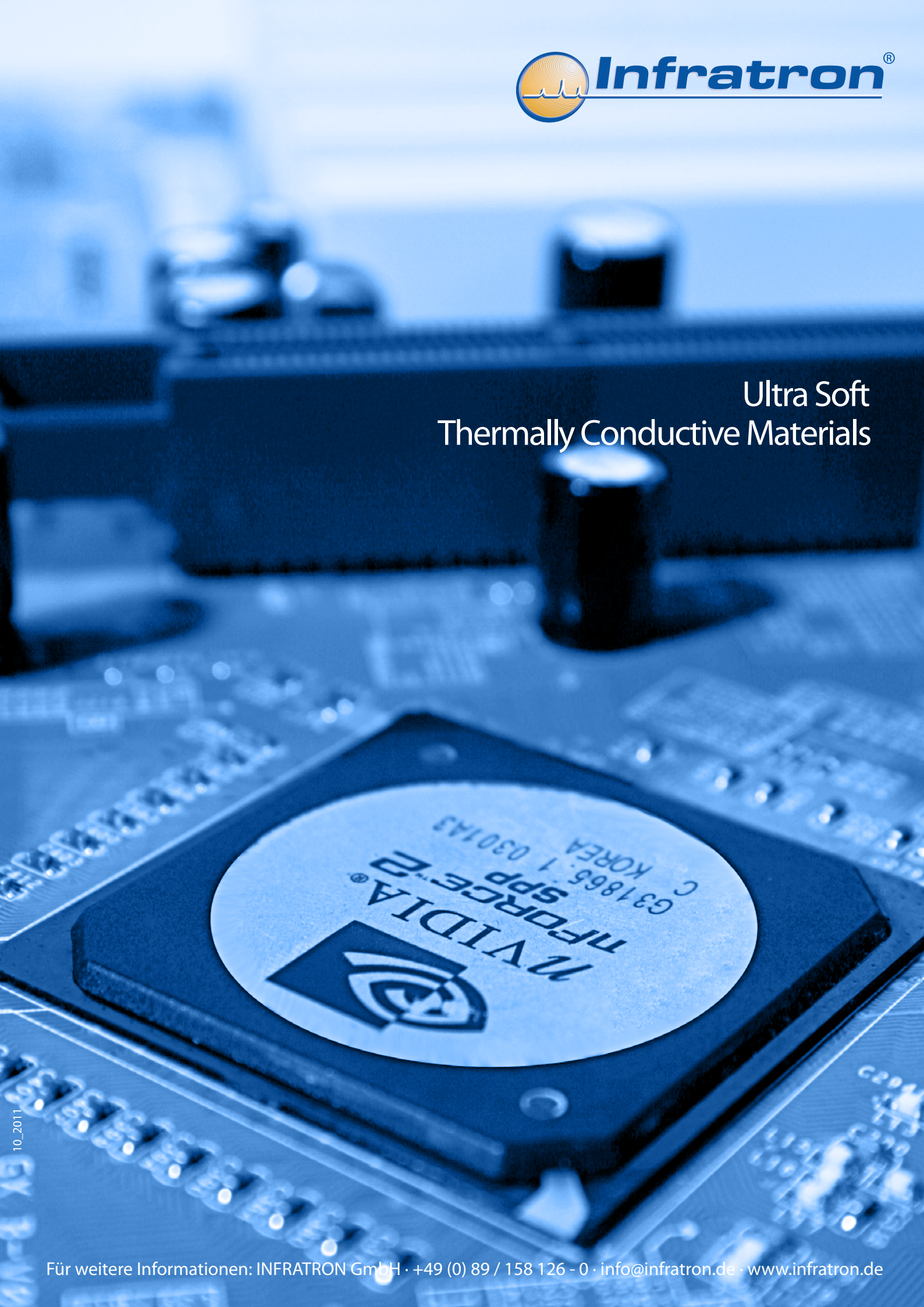
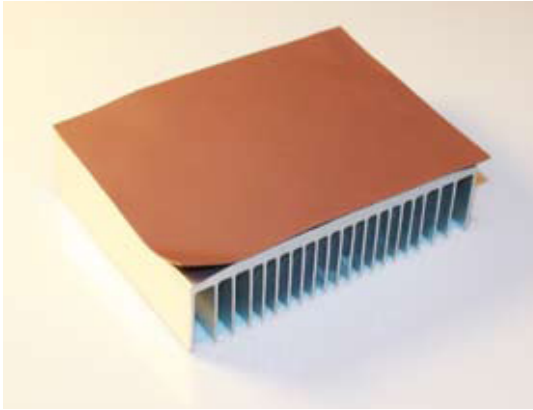


Ultra Soft Thermally Conductive Materials



10_2011

Thermal Conductive Pad



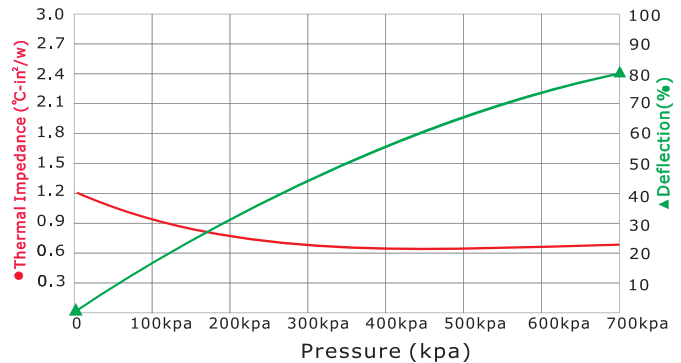
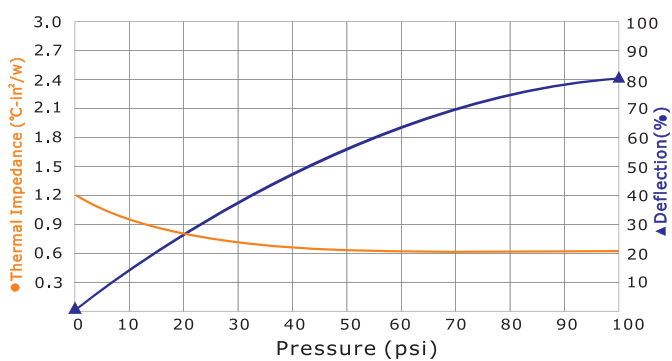
Features

Good thermal conductivity
Ultra soft and high compressibility
Natural tack
Easy to assemble
Good insulator
Shock and vibration absorber

Applications

Electronic components: IC / CPU / MOS
LED / M/B / P/S / Heat Sink / LCD-TV / Notebook PC / PC / Telecom Device /
Wireless Hub etc....
DDR II Module / DVD Applications / Hand-Set applications etc...

Thermal Resistance V.S Pressure V.S Deflection

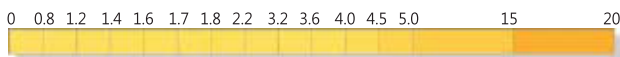


Properties

Thermal Conductivity: 2.2 W/m.k
(W / m.k - Z Axis)

REACH Compliant
RoSH Compliant

Hardness: 10 (Shore A)
(Shore A)



Testing sample thickness : 1.0 mm



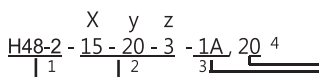
In the thermal resistance vs pressure vs deflection charts H48-2 provides low thermal impedance.

As the pressure increases the thermal impedance decreases.

H48-2 provides good compliance and softness.

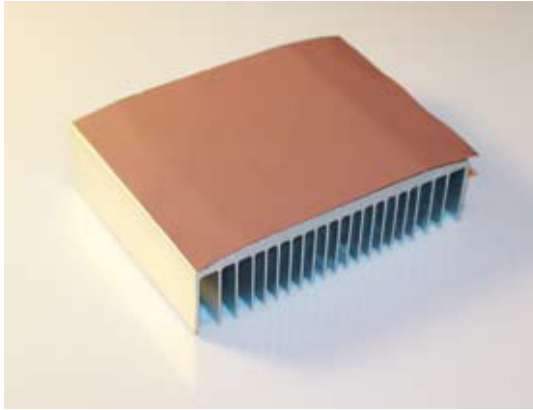
Property	L37-3	Unit	Tolerance	Test Method
Colour	Dark Red	-	-	Visual
Thickness (Available thickness range)	0.2-20	mm	-	ASTM D374
	0.0078-0.7874	inch	-	ASTM D374
Thermal Conductivity	2.2	W/m.k	-	ASTM D5470
Flame Rating	V-0	-	-	UL 94
Dielectric Breakdown Voltage	>5	kV/mm	-	ASTM D149
Weight Loss	<1	%	-	ASTM E595
Specific Gravity	2.43	g/cm ³	±0.2	ASTM D792
Working Temperature	-40 ~ +200	°C	-	-
Volume Resistance	>10 ¹²	Ohm-cm	-	ASTM D257
Elongation	282	%	±0.28	ASTM D412
Tensile Strength	7	Kgf/cm ²	±2	ASTM D412
Standard Shape	-	Sheet ones	-	-
Hardness	10	Shore A	±2	ASTM D2240

Available with an adhesive backing



1. Part Number
2. Size X-Y-Z
3. Adhesive backing - 0=None, 1A=one side, 2A=two sides
4. Quantity

Thermal Conductive Pad



Features

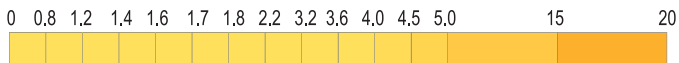
No carrier
Low contact thermal impedance
Non-Oil Bleed
High dielectric breakdown voltage

Applications

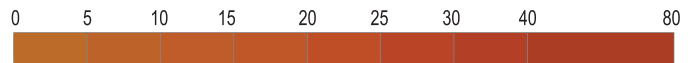
Electronic components: IC / CPU / MOS
LED / M/B / P/S / Heat Sink / LCD-TV / Notebook PC / PC / Telecom Device /
Wireless Hub etc....
DDR II Module / DVD Applications / Hand-Set applications etc...

Properties

Thermal Conductivity: 1.8 W/m.k
(W / m.k - Z Axis)



Hardeness: 60 (Shore A)
(Shore A)



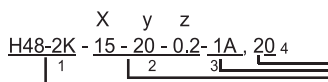
In the thermal resistance vs pressure vs deflection charts H48-2K provides low thermal impedance.

As the pressure increases the thermal impedance decreases.

H48-2K provides good compliance and softness.

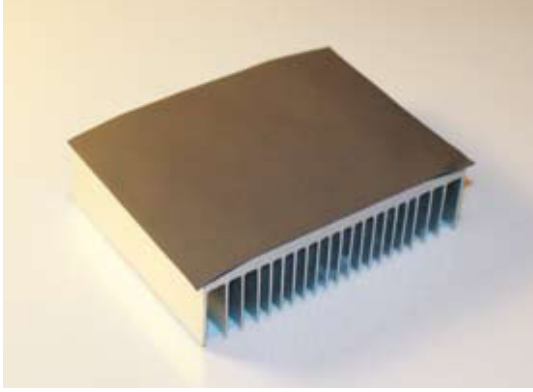
Property	H48-2K	Unit	Test Method
Thickness (+/- 10%)	0.1/0.2/0.3	mm	-
Color	Dark Red	-	Visual
Construction	Silicone based with ceramic fillers (non-silicone oil)	-	-
Opt.Temp. Range	-45 to 200	°C	-
Density	2.1	g/cm ³	ASTM D792
Thermal Conductivity	1.8	W/m.k	ASTM D5470
Hardness Shore A	60	-	ASTM D2240
Thermal impedance			ASTM D5470
10psi	0.21/0.37/0.57	K- in ² /W	-
50psi	0.20/0.33/0.51	K- in ² /W	-
100psi	0.17/0.31/0.46	K- in ² /W	-
Percent deflection			ASTM D575
10psi	2	%	-
50psi	5	%	-
100psi	11	%	-
Breakdown voltage	1.2 / 2.5 / 3.5	kV	ASTM D149
TML	< 0.5%	%	ASTM E595
Tensile strength	200	Psi	ASTM D412
Elongation	50	%	ASTM D412
UL flammability	V-0	-	UL 94

Available with an adhesive backing



1. Part Number
2. Size X-Y-Z
3. Adhesive backing - 0-None, 1A-one side, 2A-two sides
4. Quantity

Thermal Conductive Pad



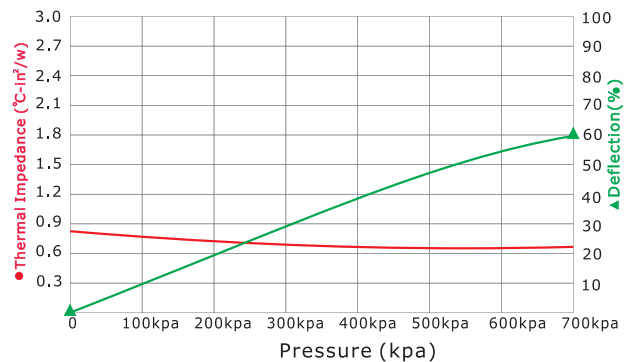
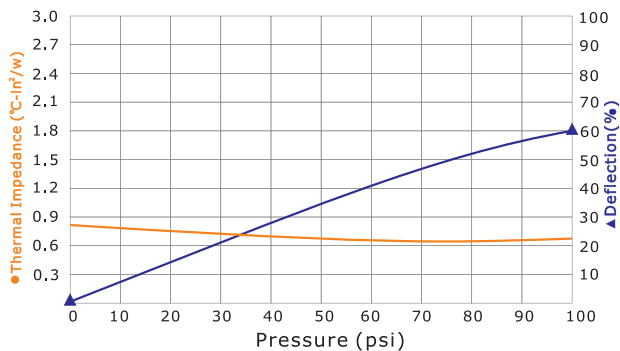
Features

Very good thermal conductivity
Soft and high compressibility
Natural tack
Easy to assemble
Very good insulator

Applications

Electronic components: IC / CPU / MOS
LED / M/B / P/S / Heat Sink / LCD-TV / Notebook PC / PC / Telecom Device /
Wireless Hub etc....
DDR II Module / DVD Applications / Hand-Set applications etc...

Thermal Resistance V.S Pressure V.S Deflection



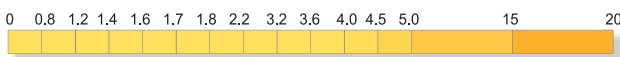
Properties

REACH Compliant

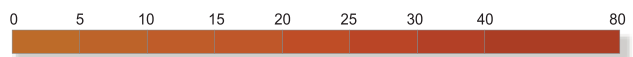
RoHS Compliant

Thermal Conductivity: 3.2 W/m.k
(W / m.k - Z Axis)

Hardeness: 20 (Shore A)
(Shore A)



Testing sample thickness : 1.0 mm



In the thermal resistance vs pressure vs deflection charts H48-6 provides low thermal impedance.

As the pressure increases the thermal impedance decreases.

H48-6 provides good compliance and softness.

Property	H48-6	Unit	Tolerance	Test Method
Colour	Dark Grey	-	-	Visual
Thickness (Available thickness range)	0.3-20	mm	-	ASTM D374
	0.0118-0.787	inch	-	ASTM D374
Thermal Conductivity	3.2	W/m.k	-	ASTM D5470
Flame Rating	V-0	-	-	UL 94
Dielectric Breakdown Voltage	>5	kV/mm	-	ASTM D149
Weight Loss	<1	%	-	ASTM E595
Specific Gravity	2.42	g/cm ³	±0.2	ASTM D792
Working Temperature	-40~ +200	°C	-	-
Volume Resistance	>10 ¹¹	Ohm-cm	-	ASTM D257
Elongation	130	%	±13	ASTM D412
Tensile Strength	8	Kgf/cm ²	±2	ASTM D412
Standard Shape	-	Sheet ones	-	-
Hardness	20	Shore A	±5	ASTM D2240

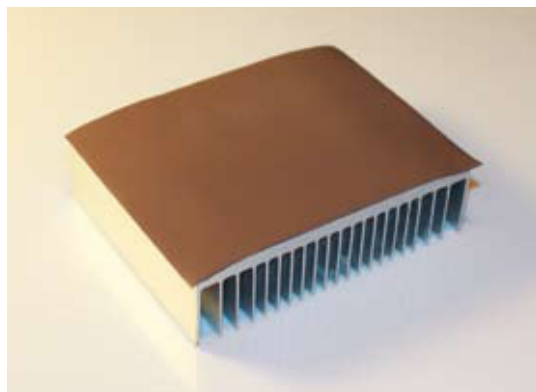
Available with an adhesive backing



X Y Z
H48-6 - 15 - 20 - 3 - 1A, 20 4
1 2 3 4

1. Part Number
2. Size X-Y-Z
3. Adhesive backing - 0=None, 1A=one side, 2A=two sides
4. Quantity

Thermal Conductive Pad



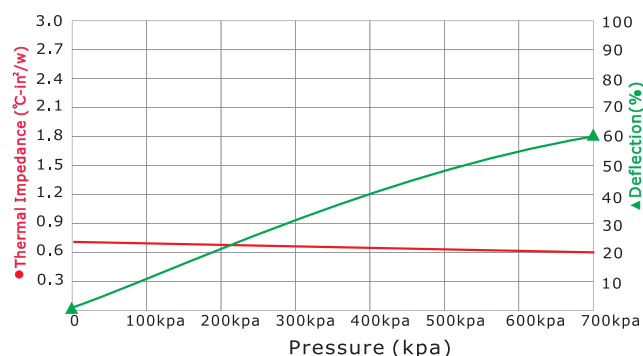
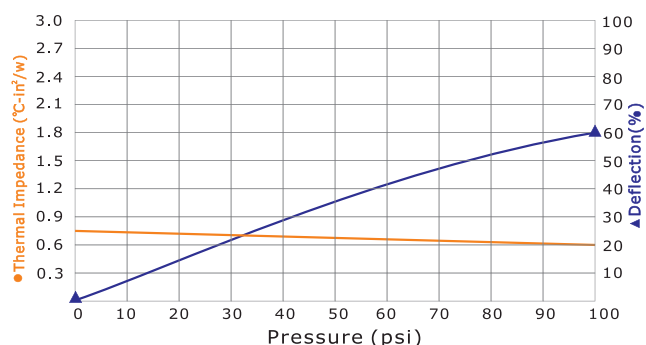
Features

Very good thermal conductivity
Soft and high compressibility
Natural tack
Easy to assemble
Very good insulator

Applications

Electronic components: IC / CPU / MOS
LED / M/B / P/S / Heat Sink / LCD-TV / Notebook PC / PC / Telecom Device /
Wireless Hub etc....
DDR II Module / DVD Applications / Hand-Set applications etc...

Thermal Resistance V.S Pressure V.S Deflection



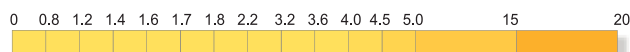
Properties

REACH Compliant

RoHS Compliant

Thermal Conductivity: 4 W/m.k
(W / m.k - Z Axis)

Hardness: 25 (Shore A)
(Shore A)



Testing sample thickness : 1.0 mm



In the thermal resistance vs pressure vs deflection charts H48-6A provides low thermal impedance.

As the pressure increases the thermal impedance decreases.

H48-6A provides good compliance and softness.

Property	H48-6A	Unit	Tolerance	Test Method
Colour	Henna	-	-	Visual
Thickness (Available thickness range)	0.3-20	mm	-	ASTM D374
	0.0118-0.787	inch	-	ASTM D374
Thermal Conductivity	4	W/m.k	-	ASTM D5470
Flame Rating	V-0	-	-	UL 94
Dielectric Breakdown Voltage	>5	kV/mm	-	ASTM D149
Weight Loss	<1	%	-	ASTM E595
Specific Gravity	2.48	g/cm ³	±0.2	ASTM D792
Working Temperature	-40~ +200	°C	-	-
Volume Resistance	>10 ¹¹	Ohm-cm	-	ASTM D257
Elongation	120	%	±13	ASTM D412
Tensile Strength	8	Kgf/cm ²	±2	ASTM D412
Standard Shape	-	Sheet ones	-	-
Hardness	25	Shore A	±5	ASTM D2240

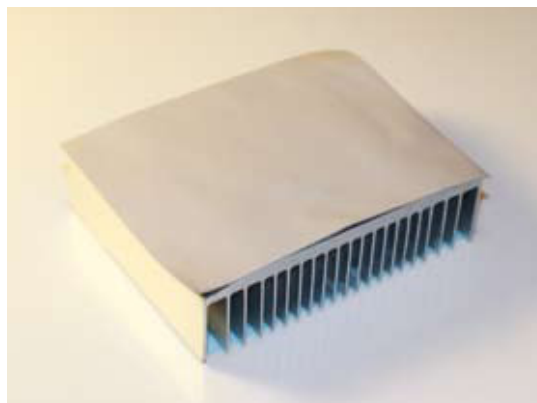
Available with an adhesive backing



H48-6A - 15 - 20 - 3 - 1A - 20 4

1. Part Number
2. Size X-Y-Z
3. Adhesive backing - 0=None, 1A=one side, 2A=two sides
4. Quantity

Thermal Conductive Pad



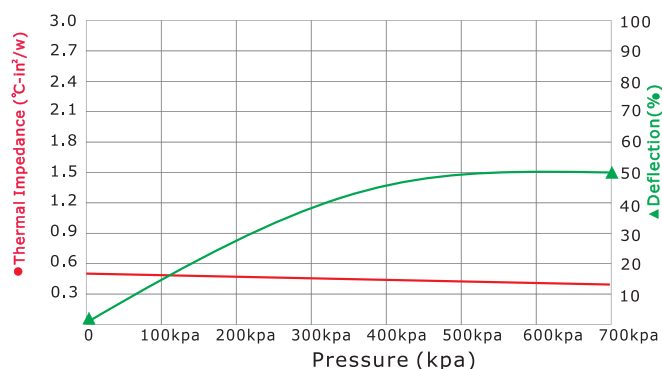
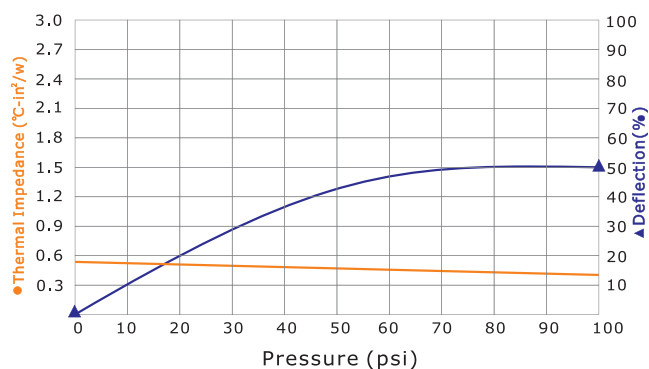
Features

Very good thermal conductivity
Soft and high compressibility
Natural tack
Easy to assemble
Very good insulator

Applications

Electronic components: IC / CPU / MOS
LED / M/B / P/S / Heat Sink / LCD-TV / Notebook PC / PC / Telecom Device /
Wireless Hub etc....
DDR II Module / DVD Applications / Hand-Set applications etc....

Thermal Resistance V.S Pressure V.S Deflection



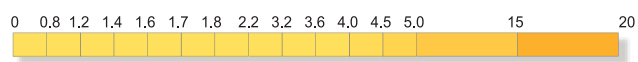
Properties

REACH Compliant

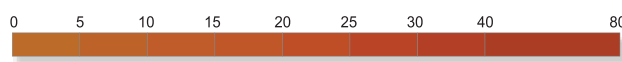
RoHS Compliant

Thermal Conductivity: 6 W/m.k
(W / m.k - Z Axis)

Hardness: 14 (Shore A)
(Shore A)



Testing sample thickness : 1 0 mm



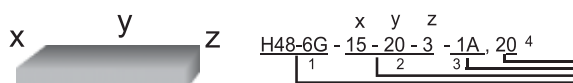
In the thermal resistance vs pressure vs deflection charts H48-6G provides low thermal impedance.

As the pressure increases the thermal impedance decreases.

H48-6G provides good compliance and softness.

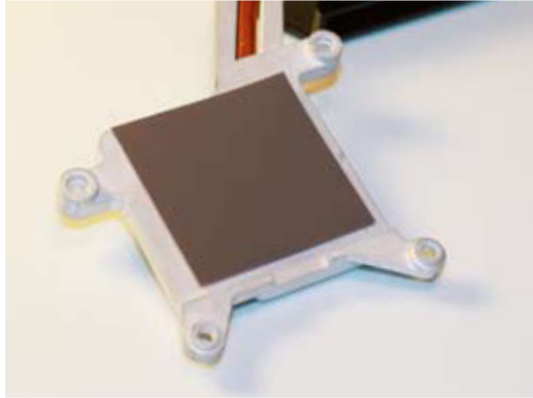
Property	H48-6G	Unit	Tolerance	Test Method
Colour	Grey	-	-	Visual
Thickness (Available thickness range)	0.3-5.0	mm	-	ASTM D374
	0.0118-0.1969	inch	-	ASTM D374
Thermal Conductivity	6	W/m.k	-	ASTM D5470
Flame Rating	V-0	-	-	UL 94
Dielectric Breakdown Voltage	>13	kV/mm	-	ASTM D149
Weight Loss	<1	%	-	ASTM E595
Specific Gravity	3.09	g/cm ³	±0.2	ASTM D792
Working Temperature	-40~ +200	°C	-	-
Volume Resistance	>10 ¹²	Ohm-cm	-	ASTM D257
Elongation	60	%	±13	ASTM D412
Tensile Strength	6	Kgf/cm ²	±2	ASTM D412
Standard Shape	-	Sheet ones	-	-
Hardness	25	Shore A	±5	ASTM D2240

Available with an adhesive backing



1. Part Number
2. Size X-Y-Z
3. Adhesive backing - 0=None, 1A-one side, 2A-two sides
4. Quantity

Thermal Conductive Pad



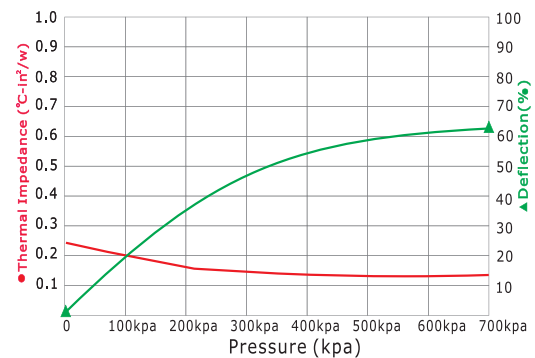
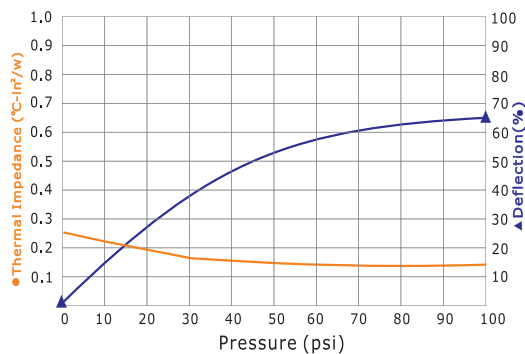
Features

Very good thermal conductivity
Very soft and compressible
Natural tack
Easy to assemble
Very good insulator

Applications

Electronic components: IC / CPU / MOS
LED / M/B / P/S / Heat Sink / LCD-TV / Notebook PC / PC / Telecom Device /
Wireless Hub etc....
DDR II Module / DVD Applications / Hand-Set applications etc...

Thermal Resistance V.S Pressure V.S Deflection



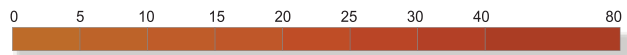
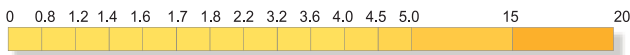
Properties

REACH Compliant

RoSH Compliant

Thermal Conductivity: 1.8 W/m.k
(W / m.k - Z Axis)

Hardness: 16 (Shore A)
(Shore A)



Testing sample thickness : 1.0 mm

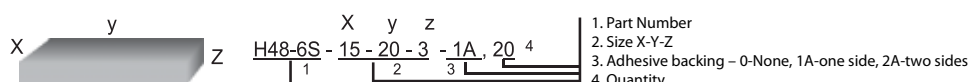
In the thermal resistance vs pressure vs deflection charts H48-6S provides low thermal impedance.

As the pressure increases the thermal impedance decreases.

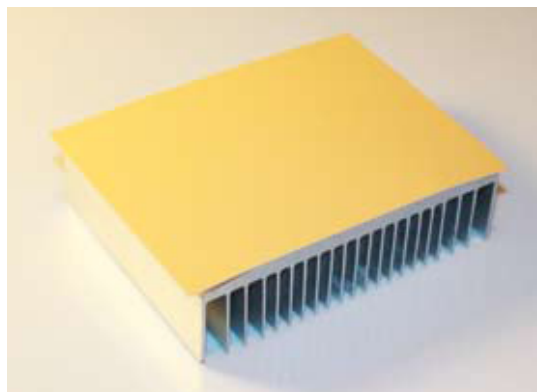
H48-6S provides good compliance and softness.

Property	H46-6S	Unit	Tolerance	Test Method
Colour	Dark red	-	-	Visual
Thickness (Available thickness range)	0.2	mm	-	ASTM D374
	0.0079	inch	-	ASTM D374
Thermal Conductivity	1.8	W/m.k	-	ASTM D5470
Flame Rating	V-0	-	-	UL 94
Dielectric Breakdown Voltage	>7	kV/mm	-	ASTM D149
Weight Loss	<1	%	-	ASTM E595
Specific Gravity	1.95	g/cm ³	±0.2	ASTM D792
Working Temperature	-40~ +200	°C	-	-
Volume Resistance	>10 ¹²	Ohm-cm	-	ASTM D257
Elongation	0.2	%	-	ASTM D412
Tensile Strength	66.5	Kgf/cm ²	±2	ASTM D412
Standard Shape	-	Sheet ones	-	-
Hardness	16	Shore A	±2	ASTM D2240

Available with an adhesive backing



Thermal Conductive Pad



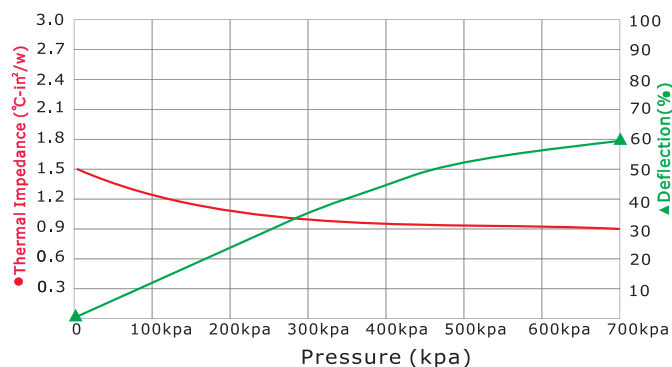
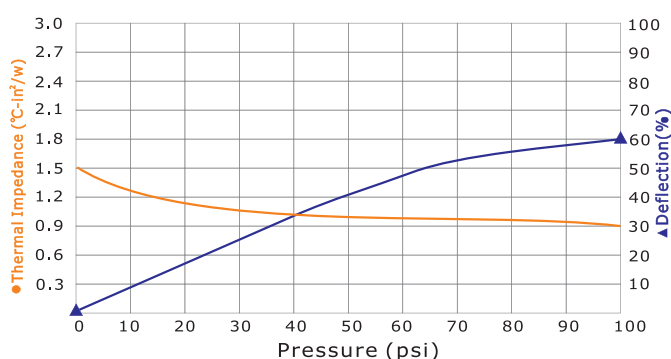
Features

Good thermal conductivity
Ultra soft and high compressibility
Natural tack
Easy to assemble
Good insulator

Applications

Electronic components: IC / CPU / MOS
LED / M/B / P/S / Heat Sink / LCD-TV / Notebook PC / PC / Telecom Device /
Wireless Hub etc....
DDR II Module / DVD Applications / Hand-Set applications etc...

Thermal Resistance V.S Pressure V.S Deflection



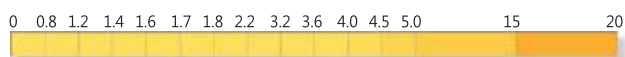
Properties

REACH Compliant

RoHS Compliant

Thermal Conductivity: 1.7 W/m.k
(W / m.k - Z Axis)

Hardness: 5 (Shore A)
(Shore A)



Testing sample thickness : 1.0 mm



In the thermal resistance vs pressure vs deflection charts L37-3 provides low thermal impedance.

As the pressure increases the thermal impedance decreases.

L37-3 provides good compliance and softness.

Property	L37-3	Unit	Tolerance	Test Method
Colour	Yellow	-	-	Visual
Reinforcement carrier	Fibreglass mesh			
Thickness (Available thickness range)	0.3-20	mm	-	ASTM D374
	0.0118~0.787	inch	-	ASTM D374
Thermal Conductivity	1.7	W/m.k	-	ASTM D5470
Flame Rating	V-0	-	-	UL 94
Dielectric Breakdown Voltage	>10	kV/mm	-	ASTM D149
Weight Loss	<1	%	-	ASTM E595
Specific Gravity	2.17	g/cm ³	±0.2	ASTM D792
Working Temperature	-40~ +200	°C	-	-
Volume Resistance	>10 ¹²	Ohm-cm	-	ASTM D257
Elongation	-	%	±0.2	ASTM D412
Tensile Strength	66.4	Kgf/cm ²	±5	ASTM D412
Standard Shape	-	Sheet ones	-	-
Hardness	5	Shore A	±3	ASTM D2240

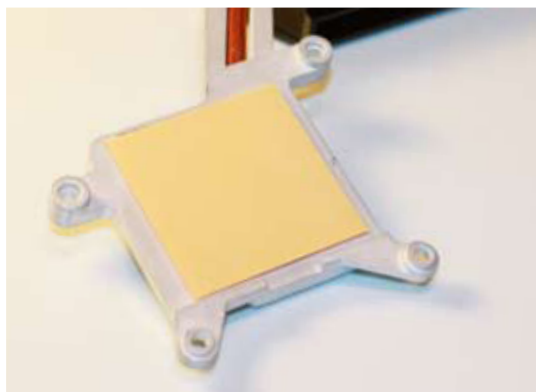
Available with an adhesive backing



X Y Z
L37-3 - 15 - 20 - 3 - 1A, 20 4
1 2 3

1. Part Number
2. Size X-Y-Z
3. Adhesive backing - 0=None, 1A=one side, 2A=two sides
4. Quantity

Thermal Conductive Pad



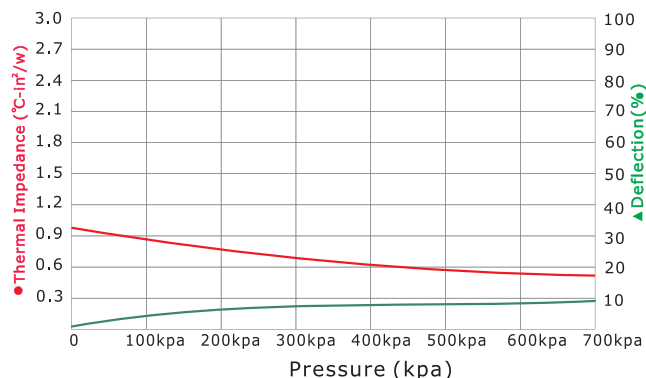
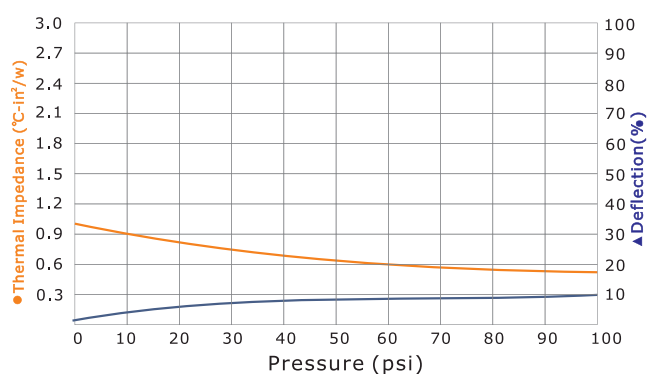
Features

Good thermal conductivity
Ultra soft and high compressibility
Natural tack
Easy to assemble
Good insulator

Applications

Electronic components: IC / CPU / MOS
LED / M/B / P/S / Heat Sink / LCD-TV / Notebook PC / PC / Telecom Device /
Wireless Hub etc....
DDR II Module / DVD Applications / Hand-Set applications etc...

Thermal Resistance V.S Pressure V.S Deflection



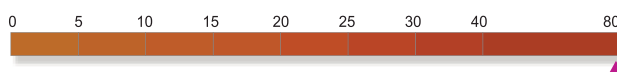
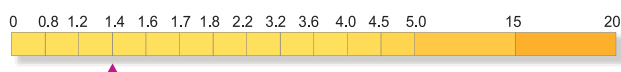
Properties

REACH Compliant

RoHS Compliant

Thermal Conductivity: 1.4 W/m.k
(W / m.k - Z Axis)

Hardness: 80 (Shore A)
(Shore A)



Testing sample thickness : 0.25 / 0.3 / 0.45mm

In the thermal resistance vs pressure vs deflection charts L37-3F provides low thermal impedance.

As the pressure increases the thermal impedance decreases.

L37-3F provides good compliance and softness.

Property	L37-3F	Unit	Tolerance	Test Method
Colour	Yellow	-	-	Visual
Thickness (Available thickness range)	0.25/0.3/0.45	mm	-	ASTM D374
	0.0098/0.0118/0.0177	inch	-	ASTM D374
Thermal Conductivity	1.4	W/m.k	-	ASTM D5470
Flame Rating	V-0	-	-	UL 94
Dielectric Breakdown Voltage	3 / 4 / 5	kV	-	ASTM D149
Weight Loss	<1	%	-	ASTM E595
Specific Gravity	2	g/cm ³	±0.2	ASTM D792
Working Temperature	-40~ +200	°C	-	-
Volume Resistance	>10 ¹³	Ohm-cm	-	ASTM D257
Elongation	5	%	±13	ASTM D412
Tensile Strength	150	Kgf/cm ²	±2	ASTM D412
Standard Shape	-	Sheet ones	-	-
Hardness	870	Shore A	±5	ASTM D2240

Available with an adhesive backing



L37-3F - 15 - 20 - 3 - 1A, 20 4

1. Part Number
2. Size X-Y-Z
3. Adhesive backing - 0=None, 1A-one side, 2A-two sides
4. Quantity

Low Bleed Thermal Pad



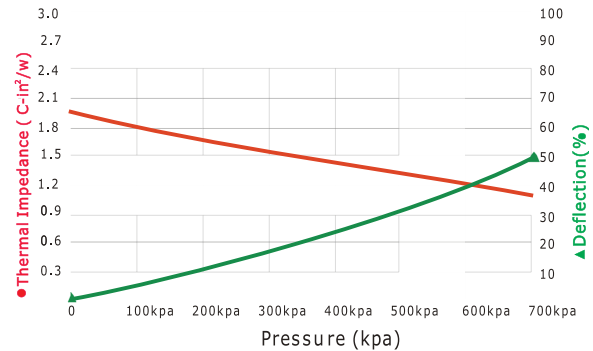
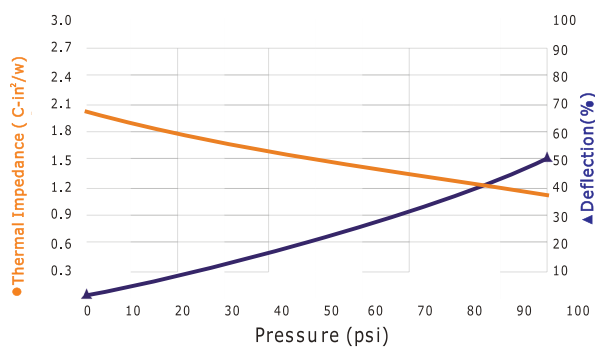
Features

Low bleed
High insulation strength
Long term stability
Low thermal resistance

Applications

Electronic components: IC / CPU / MOS
LED / M/B / P/S / Heat Sink / LCD-TV / Notebook PC / PC / Telecom Device /
Wireless Hub etc....
DDR II Module / DVD Applications / Hand-Set applications etc...

Thermal Resistance V.S Pressure V.S Deflection

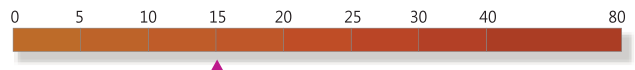
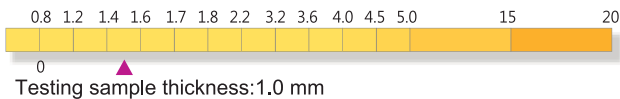


Properties

REACH Compliant
RoHS Compliant

Thermal Conductivity: 1.5 W/m.k
(W / m.k - Z Axis)

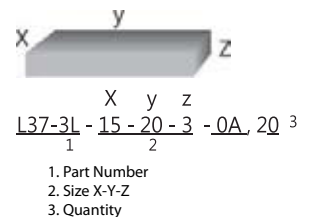
Hardness: 15 (Shore A)
(Shore A)



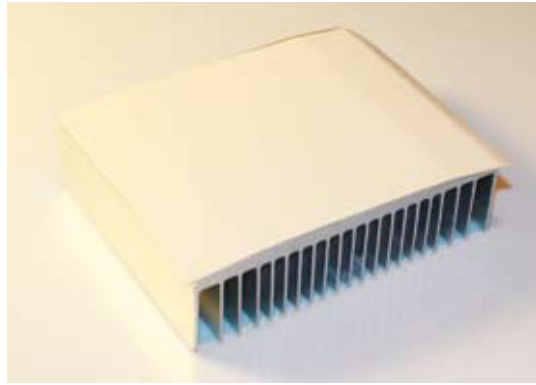
In the thermal resistance vs pressure vs deflection charts L37-3L provides low thermal impedance.
As the pressure increases the thermal impedance decreases. L37-3L provides good compliance and softness.

Property	L37-3L	Unit	Test Method
Colour	Yellow	-	Visual
Thickness (Available thickness range)	0.5-10	mm	ASTM D374
	0.0197~0.3937	inch	ASTM D374
Optimal Temperature Range	-45 to 200	°C	-
Density	2.4	g/cm ³	ASTM D792
Thermal Conductivity	1.5	W/m.k	ASTM D5470
Hardness	15	Shore A	ASTM D2240
Thermal Resistance			
T=1.0mm 10psi	2	K-in ² /W	ASTM D5470
T=1.0mm 50psi	1.5	K-in ² /W	ASTM D5470
T=1.0mm 100psi	1	K-in ² /W	ASTM D5470
Percent Deflection			
T=1.0mm 10psi	5	%	ASTM D575
T=1.0mm 50psi	20	%	ASTM D575
T=1.0mm 100psi	50	%	ASTM D575
Breakdown Voltage	15	kV/mm	ASTM D149
TML	<0.2	%	ASTM E595
Tensile Strength	1	Kgf/cm ²	ASTM D412
Elongation	300	%	ASTM D412

Available with an
adhesive backing



Thermal Conductive Pad



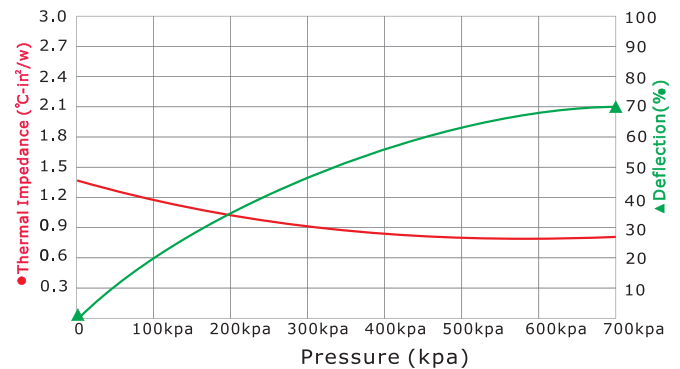
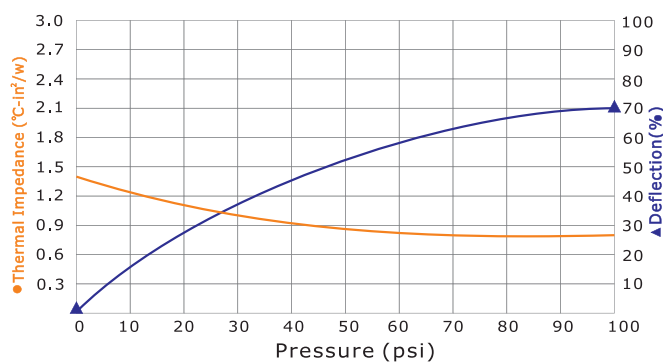
Features

Good thermal conductivity
Ultra soft and high compressibility
Natural tack
Easy to assemble
Good insulator

Applications

Electronic components: IC / CPU / MOS
LED / M/B / P/S / Heat Sink / LCD-TV / Notebook PC / PC / Telecom Device /
Wireless Hub etc....
DDR II Module / DVD Applications / Hand-Set applications etc...

Thermal Resistance V.S Pressure V.S Deflection

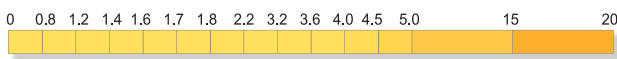


Properties

Thermal Conductivity: 1.95 W/m.k
(W / m.k - Z Axis)

REACH Compliant
RoHS Compliant

Hardness: 5 (Shore A)
(Shore A)



Testing sample thickness : 1.0 mm



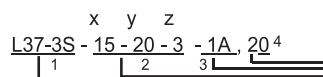
In the thermal resistance vs pressure vs deflection charts L37-3S provides low thermal impedance.

As the pressure increases the thermal impedance decreases.

L37-3S provides good compliance and softness.

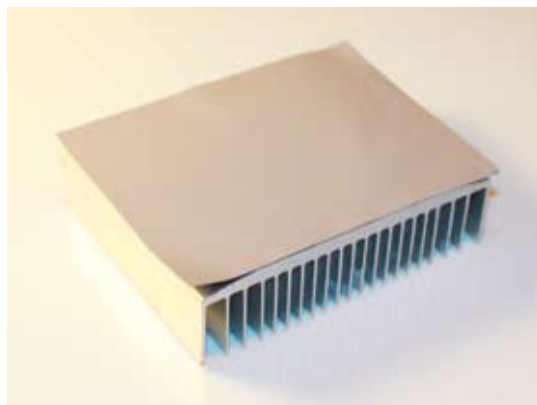
Property	L37-3S	Unit	Tolerance	Test Method
Colour	Light yellow	-	-	Visual
Thickness (Available thickness range)	0.5-20	mm	-	ASTM D374
	0.0197~0.787	inch	-	ASTM D374
Thermal Conductivity	1.95	W/m.k	-	ASTM D5470
Flame Rating	V-0	-	-	UL 94
Dielectric Breakdown Voltage	>13	kV/mm	-	ASTM D149
Weight Loss	<1	%	-	ASTM E595
Specific Gravity	2.21	g/cm ³	±0.2	ASTM D792
Working Temperature	-40~ +200	°C	-	-
Volume Resistance	>10 ¹²	Ohm-cm	-	ASTM D257
Elongation	350	%	±0.2	ASTM D412
Tensile Strength	8	Kgf/cm ²	±5	ASTM D412
Standard Shape	-	Sheet ones	-	-
Hardness	5	Shore 00	±3	ASTM D2240

Available with an adhesive backing



1. Part Number
2. Size X-Y-Z
3. Adhesive backing - 0=None, 1A=one side, 2A=two sides
4. Quantity

Thermal Conductive Pad



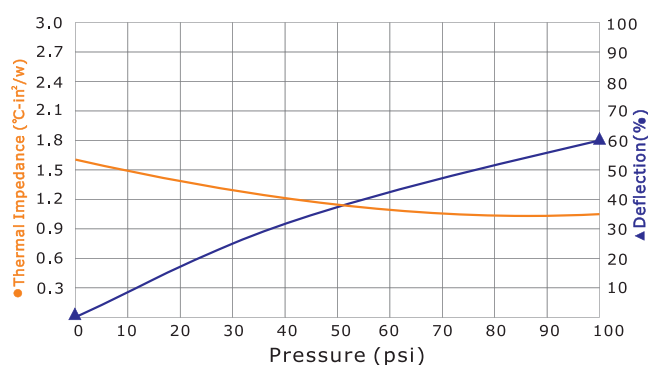
Features

Good thermal conductivity
Ultra soft and high compressibility
Natural tack
Easy to assemble
Good insulator
Shock and vibration absorber

Applications

Electronic components: IC / CPU / MOS
LED / M/B / P/S / Heat Sink / LCD-TV / Notebook PC / PC / Telecom Device /
Wireless Hub etc....
DDR II Module / DVD Applications / Hand-Set applications etc...

Thermal Resistance V.S Pressure V.S Deflection



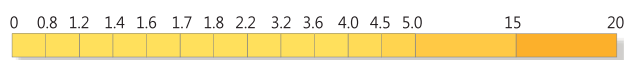
Properties

REACH Compliant

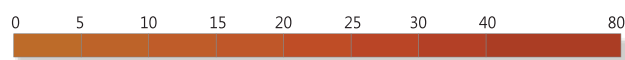
RoHS Compliant

Thermal Conductivity: 1.6 W/m.k
(W / m.k - Z Axis)

Hardness: 15 (Shore A)
(Shore A)



Testing sample thickness : 1.0 mm



In the thermal resistance vs pressure vs deflection charts L37-5 provides low thermal impedance.

As the pressure increases the thermal impedance decreases.

L37-5 provides good compliance and softness.

Property	L37-5	Unit	Tolerance	Test Method
Colour	Grey	-	-	Visual
Thickness (Available thickness range)	0.3-20	mm	-	ASTM D374
	0.0118~0.787	inch	-	ASTM D374
Thermal Conductivity	1.6	W/m.k	-	ASTM D5470
Flame Rating	V-0	-	-	UL 94
Dielectric Breakdown Voltage	>10	kV/mm	-	ASTM D149
Weight Loss	<1	%	-	ASTM E595
Specific Gravity	2.38	g/cm ³	±0.2	ASTM D792
Working Temperature	-40~ +200	°C	-	-
Volume Resistance	>10 ¹²	Ohm-cm	-	ASTM D257
Elongation	300	%	±0.2	ASTM D412
Tensile Strength	12	Kgf/cm ²	±5	ASTM D412
Standard Shape	-	Sheet ones	-	-
Hardness	15	Shore 00	±3	ASTM D2240

Available with an adhesive backing



X Y Z
L37-5 - 15 - 20 - 3 - 1A, 20 4
1 2 3L

1. Part Number
2. Size X-Y-Z
3. Adhesive backing - 0=None, 1A=one side, 2A=two sides
4. Quantity

High Power LED Ceramic Core PCB



Product

These ceramic circuit boards are sintered at 1450C. Circuits on the surface are printed using silver via a nickel and tin coating process. This gives superior thermal conductivity and electrical performance.

Features

Hot and cold impact resistance
Low CTE
UV resistant
Chemically and Environmentally resistant

Applications

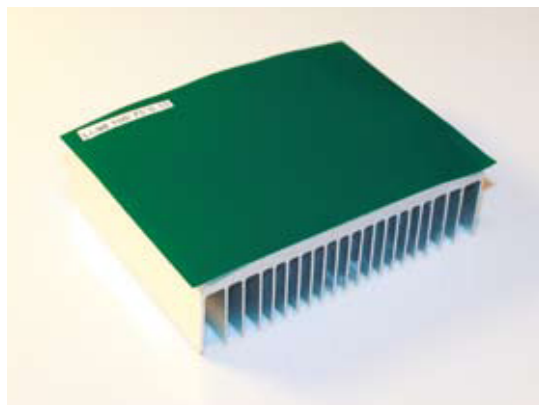
Electronic components: IC/CPU/MOS
LED / M/B / P/S / Heat sink / LCD-TV / Notebook PC / PC / Telecom device / Wireless Hub / etc...
DDR II Module / DVD Applications / Hand-set Applications / etc...

Caution

After opening the package, the LED CPCB should be kept at 30% RH or less.

Properties

Functional Characteristics	CP-20	CP-57
Insulation Resistance	>100G (1000VDC, 1 minute)	>10G (1000VDC, 1 minute)
Dielectric with standing voltage	Ok (1500VAC, 60 HZ, 1 minute)	Ok (1500VAC, 60HZ, 1 minute)
Thermal Conductivity	$\geq 8\text{W/mk}$	$\geq 10\text{W/mk}$
Solder Heat Resistance	300 °C / 5 sec	300 °C / 5 sec
Electrode Tensile Strength	> WB 20N (2Gf)	> WB 20N (2Gf)
Density	$\geq 3.2\text{g/cm}^3$	$\geq 2.5\text{g/cm}^3$
Porosity	$\geq 15\%$	$\geq 15\%$
RoHS Compliant	Yes	Yes
Bending Strength	> WB 100N (10KGf)	> WB 100N (10KGf)
Dimension	Ø20mm (2.0mm)x t2.0mm (max)	Ø53mm (2.0mm)x t2.0mm (max)



Features

Good adhesion
Very good thermal conductivity
Highly compressible
Easy to assemble

Applications

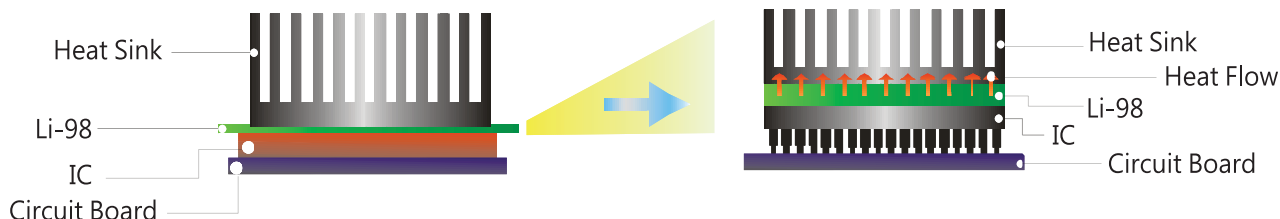
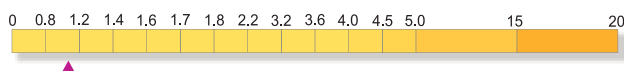
Electronic components: IC / CPU / MOS
LED / M/B / P/S / Heat Sink / LCD-TV / Notebook PC / PC / Telecom Device /
Wireless Hub etc...
DDR II Module / DVD Applications / Hand-Set applications etc...

Properties

REACH Compliant

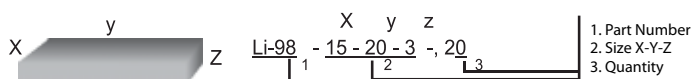
RoHS Compliant

Thermal Conductivity: 0.95 W/m.k
(W / m.k - Z Axis)



Property	Li-98		Li-98C	Li98CN	Unit	Test Method
Thickness	0.15	0.25	0.2	0.18		ASTM D374
Colour	White	White	White	White		Visual
Reinforcement carrier	Fibreglass mesh					
Density	1.85	1.85	1.9	1.8	g/cm ³	ASTM D792
Tensile strength	200	400	200	50	psi	ASTM D412
Glass transition temperature	-30	-30	-27	-30	°C	
Short time use temperature (30sec)	200	200	200	200	°C	
Continuous working temperature	-30 to 120	-30 to 120	-30 to 120	-30 to 120	°C	
Thermal conductivity	0.95	0.95	1.8	2	W/mK	ASTM D5470
Thermal impedance @ <1psi	1.0	1.8	0.7	0.6	C in 2/W	ASTM D5470
Thermal impedance @ 50psi	0.9	1.5	0.5	0.3	C in 2/W	ASTM D5470
Initial tack	11	10	14	15	cm	PSTC-6
Lap shear strength	61	61	65	55	N/cm ²	ASTM D1002
Die shear strength @ 25 °C	120	120	118	100	N/cm ²	-
Die shear strength @ 80 °C	69	69	68	55	N/cm ²	-
Holding power 1000g @ 25 °C using 1 in ²	>10000	>10000	>10000	>10000	min	PSTC-7
Holding power 1000g @ 80 °C using 1 in ²	>10000	>10000	>10000	>10000	min	PSTC-7
180° peeling strength (aluminium)	4	5	4	3	N/cm	ASTM D3330
Dielectric breakdown voltage (Vac)	>2	>3	>3	>5	kV	ASTM D149
Dielectric breakdown voltage (Vdc)	>3	>4	>4	>6	kV	ASTM D149

Available with an adhesive backing



15 Li-2000

Thermal Tape



Features

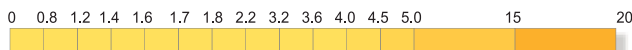
Good adhesion
Low contact thermal impedance
High thermal conductivity
High bond strength
High temp-long term stability
Electrically insulating

Applications

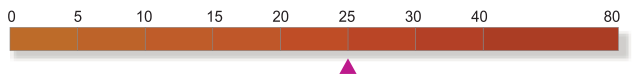
Electronic components: IC / CPU / MOS / LED / M/B / P/S / Heat Sink
LCD-TV / Notebook PC / PC / Telecom Device / Wireless Hub etc....
DDR II Module / DVD Applications / Hand-Set applications etc....

Properties

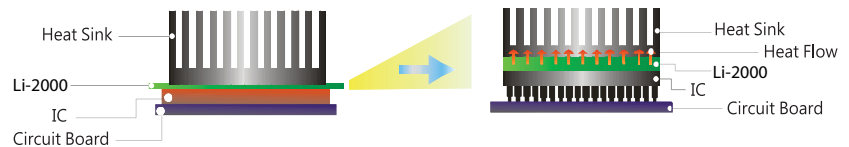
Thermal Conductivity: 1.0 W/m.k



Hardeness: (Shore A)

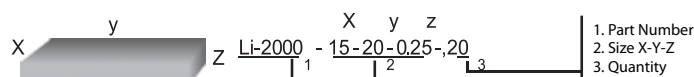


REACH Compliant RoHS Compliant



Property	Li-2000		Unit	Test Method
Colour	White	White	-	Visual
Reinforcement Carrier	Fibreglass	Fibreglass	-	-
Thickness	0.15	0.25	mm	ASTM D374
Continuous working temperature	-45~170	-45~170	°C	-
Short term use temperature	260	260	°C	-
Initial Tack	10	10	cm	PSRC-6
Lap shear strength	74	76	N/cm ²	D1002
Die Sheer strength @ 25 °c	113	126	N/cm ²	-
Die Sheer strength @ 80 °c	80	85	N/cm ²	-
Die Sheer strength @ 150 °c	30	35	N/cm ²	-
Holding Power 1kg @ 25 °c	>40000	>40000	min	PSCT-7
Holding Power 1kg @ 80 °c	>40000	>40000	min	PSCT-7
Holding Power 1kg @ 150 °c	>10000	>10000	min	PSCT-7
Tensile Strength	6	6	N/mm ²	ASTM D412
Elongation	70	70	%	ASTM D412
Dielectric strength	>2	>3	KV/mm	ASTM D149
Volume resistivity	>10 ¹¹	>10 ¹¹	Ohm-cm	ASTM D257
Thermal conductivity	1.2	1.2	W/m*K	ASTM D5470
0psi thermal resistance	0.90	1.40	0°C in ² /W	ASTM D5470
10psi thermal resistance	0.81	1.30	0°C in ² /W	ASTM D5470
30psi thermal resistance	0.76	1.16	0°C in ² /W	ASTM D5470
50psi thermal resistance	0.73	0.90	0°C in ² /W	ASTM D5470
70psi thermal resistance	0.68	0.86	0°C in ² /W	ASTM D5470
100psi thermal resistance	0.54	0.80	0°C in ² /W	ASTM D5470
Flame rating	V-1	V-1	-	UL94

Available with an adhesive backing



16 Li-2000A

Thermal Tape



Features

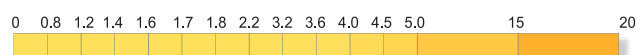
Good adhesion
Low contact thermal impedance
High thermal conductivity
High bond strength
High temp-long term stability
Electrically insulating

Applications

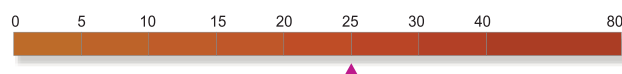
Electronic components: IC / CPU / MOS / LED / M/B / P/S / Heat Sink
LCD-TV / Notebook PC / PC / Telecom Device / Wireless Hub etc....
DDR II Module / DVD Applications / Hand-Set applications etc....

Properties

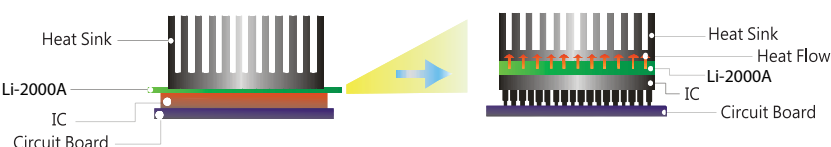
Thermal Conductivity: 1.9 W/m.k



Hardness: (Shore A)

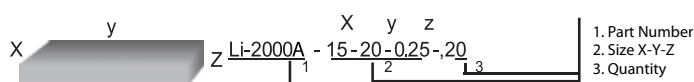


REACH Compliant RoHS Compliant



Property	Li2000A	Unit	Test Method
Colour	White	-	Visual
Reinforcement Carrier	-	-	
Thickness	0.2	mm	ASTM D374
Continuour working temperature	-45~170	°C	-
Short term use temperature	260	°C	-
Initial Tack	>30	cm	PSTC-6
Lap shear strength	35	N/cm ²	D1002
Die Sheer strength @ 25°C	60	N/cm ²	-
Die Sheer strength @ 80°C	50	N/cm ²	-
Die Sheer strength @150°C	40	N/cm ²	-
Holding Power 100g @ 25 °c using 1in ²	>40000	min	PSTC-7
Holding Power 100g @ 80 °c using 1in ²	>40000	min	PSTC-7
Holding Power 100g @ 150 °c using 1in ²	>10000	min	PSTC-7
Dielectric Breakdown Voltage (Vac)	>3.5	kV	ASTM D149
Dielectric Breakdown Voltage (Vdc)	>4.5	kV	ASTM D149
Volume Resistance	>10 ¹¹	Ohm-cm	ASTM D257
Thermal Conductivity	2	W/m*K	ASTM D5470
Thermal Impedance @ <1psi	0.7	°c in ² /W	ASTM D5470
Thermal Impedance @ 10psi	0.63	°c in ² /W	ASTM D5470
Thermal Impedance @ 30psi	0.54	°c in ² /W	ASTM D5470
Thermal Impedance @ 50psi	0.45	°c in ² /W	ASTM D5470
Thermal Impedance @ 70psi	0.4	°c in ² /W	ASTM D5470
Thermal Impedance @ 100psi	0.35	°c in ² /W	ASTM D5470
Flame rating	V-0	-	UL94

Available with an adhesive backing



Non-Silicone Thermal Conductive Pad



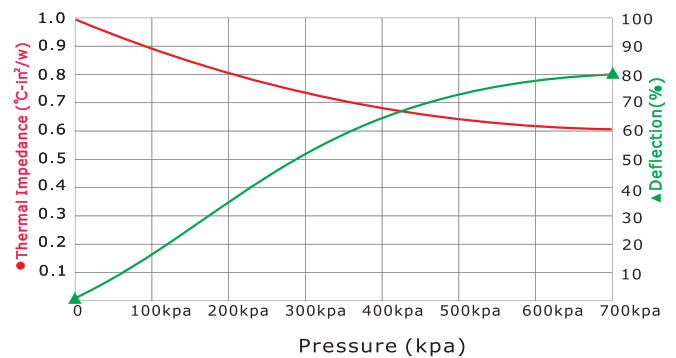
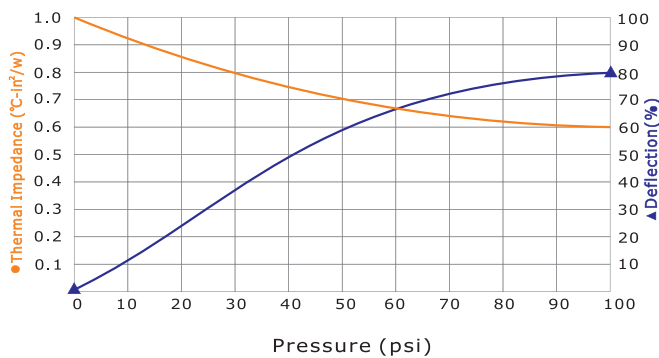
Features

Low contact thermal impedance
Good thermal conductivity
Silicone free
Long term stability

Applications

Electronic components: IC / CPU / MOS
LED / M/B / P/S / Heat Sink / LCD-TV / Notebook PC / PC / Telecom Device /
Wireless Hub etc....
DDR II Module / DVD Applications / Hand-Set applications etc...

Thermal Resistance V.S Pressure V.S Deflection



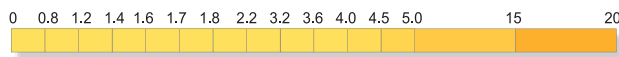
Properties

REACH Compliant

RoHS Compliant

Thermal Conductivity: 2 W/m.k
(W / m.k - Z Axis)

Hardness: 60 (Shore 00)
(Shore 00)



Testing sample thickness : 1.0 mm

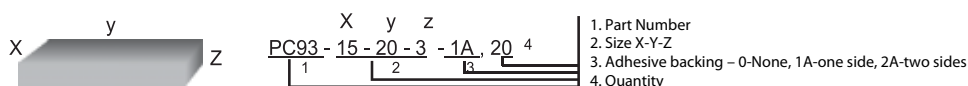


In the thermal resistance vs pressure vs deflection charts PC93 provides low thermal impedance.

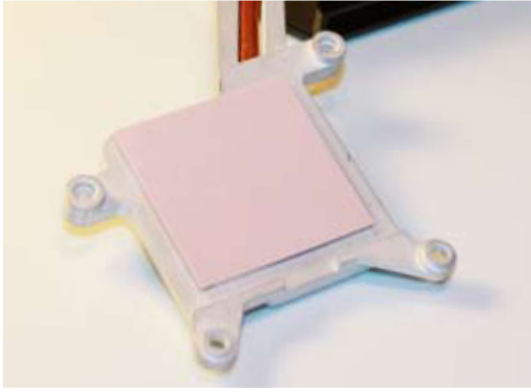
As the pressure increases the thermal impedance decreases. PC93 provides good compliance and softness.

Property	PC93	Unit	Tolerance	Test Method
Colour	Grey	-	-	Visual
Thickness (Available thickness range)	0.25 ~ 5.0	mm	-	ASTM D374
	0.0098~0.1969	inch	-	ASTM D374
Thermal Conductivity	2	W/m.k	-	ASTM D5470
Flame Rating	V-0	-	-	UL 94
Dielectric Breakdown Voltage	10	kV/mm	-	ASTM D149
Weight Loss	<1	%	-	ASTM E595
Specific Gravity	1.5	g/cm ³	±0.2	ASTM D792
Working Temperature	-30~ 150	°C	-	-
Volume Resistance	>10 ¹²	Ohm-cm	-	ASTM D257
Elongation	350	%	±13	ASTM D412
Tensile Strength	1	Kgf/mm ²	±2	ASTM D412
Standard Shape	-	Sheet ones	-	-
Hardness	60	Shore 00	±5	ASTM D2240

Available with an adhesive backing



Non-Silicone Thermal Conductive Pad



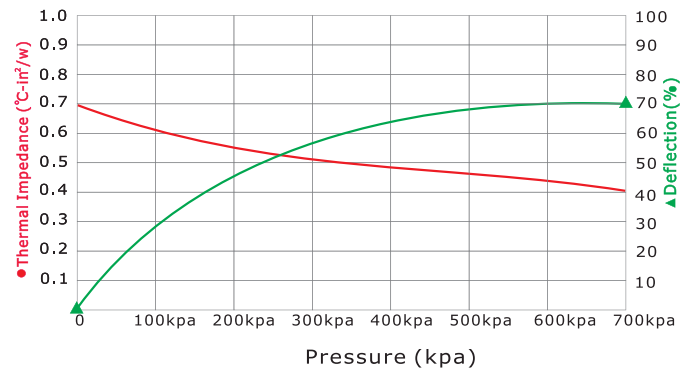
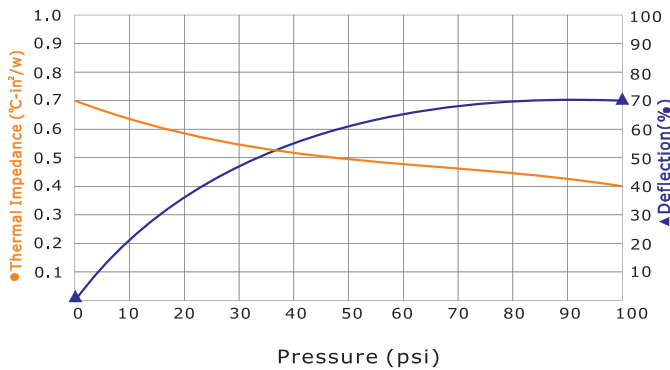
Features

Low contact thermal impedance
Good thermal conductivity
Silicone free
Long term stability

Applications

Electronic components: IC / CPU / MOS
LED / M/B / P/S / Heat Sink / LCD-TV / Notebook PC / PC / Telecom Device /
Wireless Hub etc....
DDR II Module / DVD Applications / Hand-Set applications etc....

Thermal Resistance V.S Pressure V.S Deflection



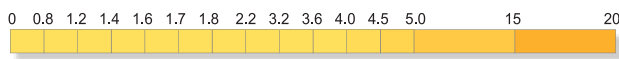
Properties

REACH Compliant

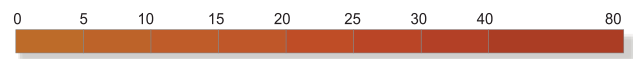
RoHS Compliant

Thermal Conductivity: 4 W/m.k
(W / m.k - Z Axis)

Hardness: 60 (Shore 00)
(Shore 00)



Testing sample thickness : 1.0 mm



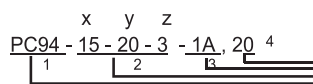
In the thermal resistance vs pressure vs deflection charts PC94 provides low thermal impedance.

As the pressure increases the thermal impedance decreases.

PC94 provides good compliance and softness.

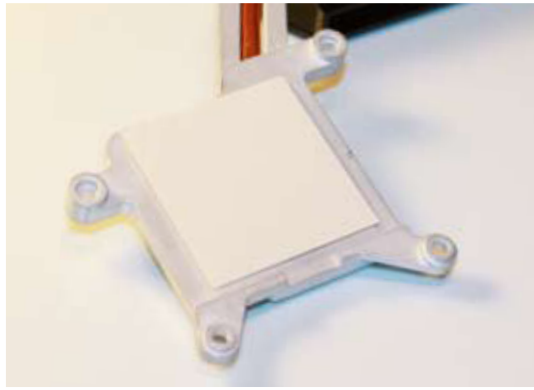
Property	PC94	Unit	Tolerance	Test Method
Colour	Red	-	-	Visual
Thickness (Available thickness range)	0.25 / 5.0	mm	-	ASTM D374
	0.0098 / 0.1969	inch	-	ASTM D374
Thermal Conductivity	4	W/m.k	-	ASTM D5470
Flame Rating	V-1	-	-	UL 94
Dielectric Breakdown Voltage	10	kV/mm	-	ASTM D149
Weight Loss	<1	%	-	ASTM E595
Specific Gravity	2.5	g/cm ³	±0.2	ASTM D792
Working Temperature	-40~ 105	°C	-	-
Volume Resistance	>10 ¹⁰	Ohm-cm	-	ASTM D257
Elongation	100	%	±13	ASTM D412
Tensile Strength	2	Kgf/cm ²	±2	ASTM D412
Standard Shape	-	Sheet ones	-	-
Hardness	60	Shore 00	±5	ASTM D2240

Available with an adhesive backing



1. Part Number
2. Size X-Y-Z
3. Adhesive backing – 0=None, 1A=one side, 2A=two sides
4. Quantity

Phase Change Material





Features

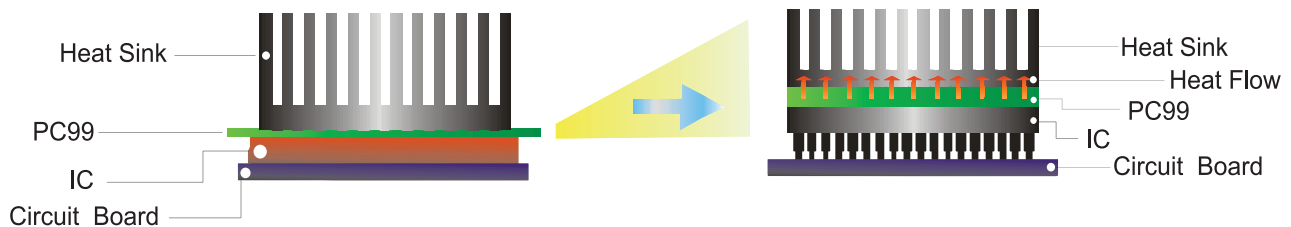
Low thermal resistance
Natural tack

Applications

Electronic components: IC / CPU / MOS
LED / M/B / P/S / Heat Sink / LCD-TV / Notebook PC / PC / Telecom Device /
Wireless Hub etc....
DDR II Module / DVD Applications / Hand-Set applications etc...

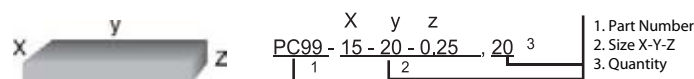
Properties

-  REACH Compliant
-  RoHS Compliant



Property	PC99	Unit	Tolerance	Test Method
Colour	Yellow	-	-	Visual
Thickness (Available thickness range)	0.06 / 0.12	mm	-	ASTM D374
	0.0024/0.0047	inch	-	ASTM D374
Appearance	Sticky	-	-	Visual
Phase change softening point	52	°C	-	-
Specific Gravity	2.35	g/cm ³	±0.2	ASTM D792
Working Temperature	-40~ 200	°C	-	-
Surface Resistance	>10 ¹²	Ohm-cm	-	ASTM D257
Elongation	5	%	±13	ASTM D412
Tensile Strength	0.1	Kgf/cm ²		ASTM D412
Standard Shape	-	Sheet ones	-	-
Thermal Resistance 30psi	0.1	°C-cm ² /w	-	-

Available with an adhesive backing







Features

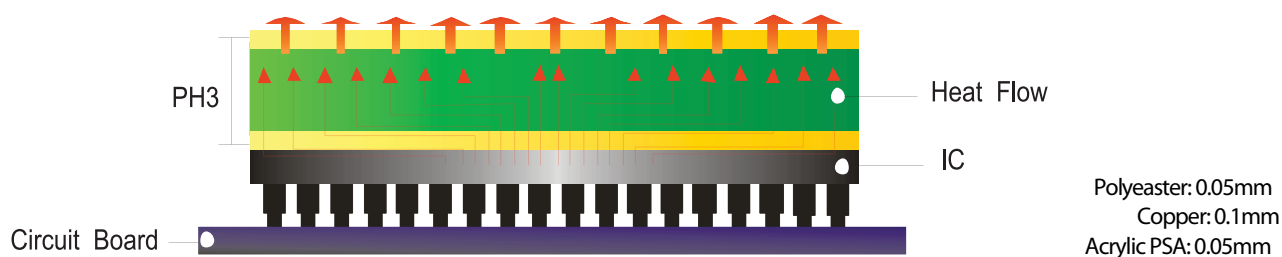
Gives a typical junction temperature reduction of 20C
 Gives design flexibility
 Die cut for custom shapes

Applications

Electronic components: IC / CPU / MOS
 LED / M/B / P/S / Heat Sink / LCD-TV / Notebook PC / PC / Telecom Device /
 Wireless Hub etc....
 DDR II Module / DVD Applications / Hand-Set applications etc...

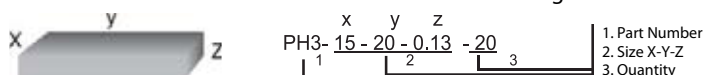
Properties

-  REACH Compliant
-  RoHS Compliant



Property	PH3	Unit
Colour	Black	-
Thickness	0.21	mm
Thermal Conductor	Copper	-
Thermal Conductor Thickness	0.1	mm
Insulator	Polyester	-
Insulator Thickness	0.05	mm
Pressure-sensitive Adhesive (PSA) system	Acrylic PSA	-
PSA thickness	0.05	mm
Dielectric Breakdown Voltage	3.5	kV
Specific Gravity	7.5	g/cm ³

Available with an adhesive backing



Thermal Compound



Features

Good thermal conductivity
Easy to assemble
High stability
Does not harden with time

Applications

Electronic components: IC / CPU / MOS
LED / M/B / P/S / Heat Sink / LCD-TV / Notebook PC / PC / Telecom Device /
Wireless Hub etc....
DDR II Module / DVD Applications / Hand-Set applications etc...

Storage

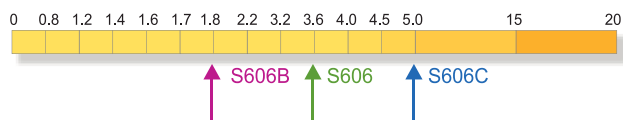
S606 has a self-life of eighteen (18) months from the date of manufacture, as indicated by the lot number, when stored in the original, unopened container at, or below 25 °C.



Properties

REACH Compliant
RoHS Compliant

Thermal Conductivity: (W / m.k - Z Axis)

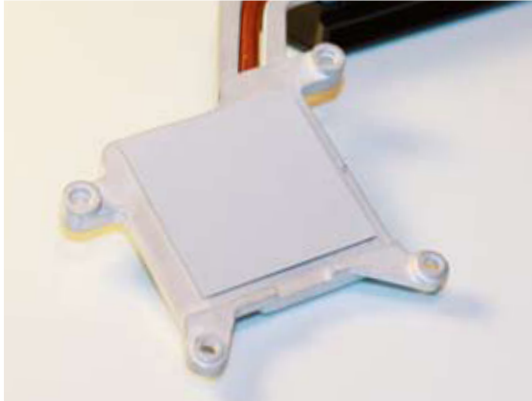


S606B Thermal Conductivity 1.8 W/m.k
S606 Thermal Conductivity 3.6 W/m.k
S606C Thermal Conductivity 5.0 W/m.k

Property	S606	S606B	S606C	Unit	Test Method
Colour	White	White	Grey	-	Visual
Thermal Conductivity	3.6	1.8	5	W/m.k	ASTM D5470
Weight Loss	<0.5	<0.5	<0.5	%	ASTM E595
Specific Gravity	2.3	2.3	2.3	g/cm ³	ASTM D792
Working Temperature	-40~ +180	-40~ +180	-40~ +180	°C	-
Volume Resistance	>10 ¹²	>10 ¹²	>10 ¹²	Ohm-cm	ASTM D257
Standard Package	1kg	1kg	1kg	kg/pot	-

S606(C) - 30 gram
1. Part Number
2. Quantity

Thermally Conductive Insulators



Features

High Insulation Strength
Low thermal resistance
Easy to assemble

Applications

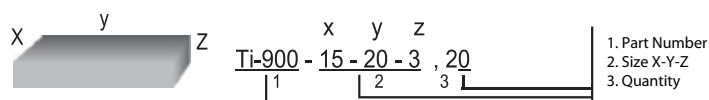
Electronic components: IC / CPU / MOS
LED / M/B / P/S / Heat Sink / LCD-TV / Notebook PC / PC / Telecom Device /
Wireless Hub etc....
DDR II Module / DVD Applications / Hand-Set applications etc...

Properties

	Ti900	Test Methods
Viscose	One Side	ASTM D374
Thickness (mm)	0.12	-
Base	RITF	-
Thermal Conductivity w/m K*1	1.8	ASTM D5470
Thermal Resistance @ 10psi (K in ² / W)	0.50	ASTM D5470
Thermal Resistance @ 30psi (K in ² / W)	0.42	ASTM D5470
Thermal Resistance @ 50psi (K in ² / W)	0.35	ASTM D5470
Thermal Resistance @ 100psi (K in ² / W)	0.29	ASTM D5470
Thermal Resistance @ 200psi (K in ² / W)	0.28	ASTM D5470
Thermal Resistance @ 400psi (K in ² / W)	0.27	ASTM D5470
Insulation Strength Vac, V	>6000	ASTM D149
Volume resistance Ohm-cm	>10 ¹²	ASTM D257
Working Temperature	-50 to 180	°C
Tensile Strength	5000 psi	ASTM D412
Elongation	40%	ASTM D412
Flame rating UL	Pending (as V-0)	UL94

Available with an adhesive backing

*1 Measured using a method ASTM D5470-06 sample size 1 in²



23 T62

Graphite Sheets





Features

Ultra high thermal conductivity
Easy to assemble

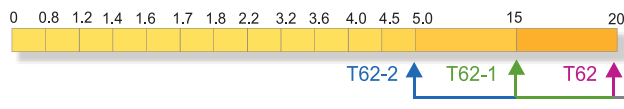
Applications

Electronic components: IC / CPU / MOS
LED / M/B / P/S / Heat Sink / LCD-TV / Notebook PC / PC / Telecom Device /
Wireless Hub etc....
DDR II Module / DVD Applications / Hand-Set applications etc...

Properties

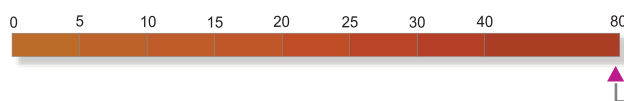
-  REACH Compliant
-  RoHS Compliant

Thermal Conductivity: (W / m.k - Z Axis)

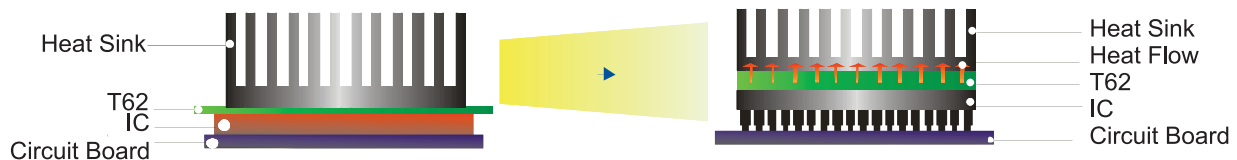


T62-2 Thermal Conductivity 5.0 W/m.k
T62-1 Thermal Conductivity 15.0 W/m.k
T62 Thermal Conductivity 20.0 W/m.k

Hardness: 80 (Shore A)
(Shore A)

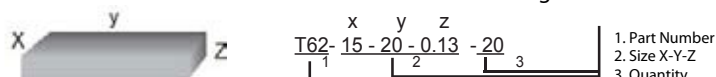


T62 2 Hardness 80 (Shore A)
T62-1 Hardness 80 (Shore A)
T62 Hardness 80 (Shore A)

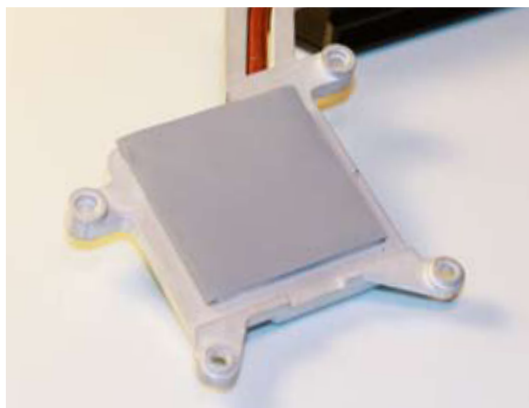


Property	T62	T62-1	T62-2	Unit
Type	Graphite	Graphite + adhesive	PET+Graphite+adhesive	-
Color	Black	Black	Black	
Thickness	0.13	0.16	0.2	mm
	0.005	0.0063	0.0079	inch
Thermal Conductvity	X-Y, 400	X-Y, 400	X-Y, 400	W/m.k
	Z,20	Z,15	Z,5	W/m.k
Flame Rating	V-0	V-0	V-0	UL 94
Specific Gravity	1.5~1.8			g/cm ³
Graphite Contained	>98%	>98%	>98%	%
Hardness	80	80	80	Shore A

Available with an adhesive backing



Ultra Soft Thermal Conductive Pad



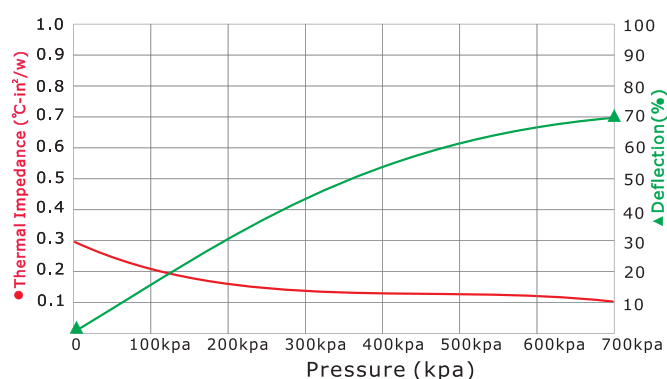
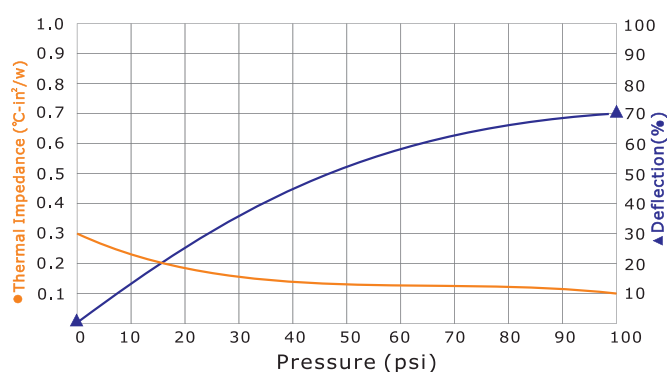
Features

Superior thermal conductivity
Highly compressible
Naturally tacky
Low Shore 00 hardness
Low oil bleed
Electrically insulating

Applications

Electronic components: IC / CPU / MOS
LED / M/B / P/S / Heat Sink / LCD-TV / Notebook PC / PC / Telecom Device /
Wireless Hub etc....
DDR II Module / DVD Applications / Hand-Set applications etc...

Thermal Resistance V.S Pressure V.S Deflection



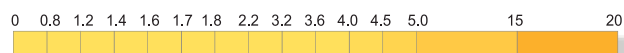
Properties

Thermal Conductivity: 1.0 W/m.k
(W / m.k - Z Axis)

REACH Compliant

RoHS Compliant

Hardeness: 60 (Shore 00)
(Shore 00)



Testing sample thickness : 1.0 mm



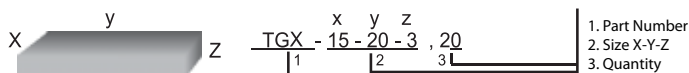
In the thermal resistance vs pressure vs deflection charts TG-X provides low thermal impedance.

As the pressure increases the thermal impedance decreases.

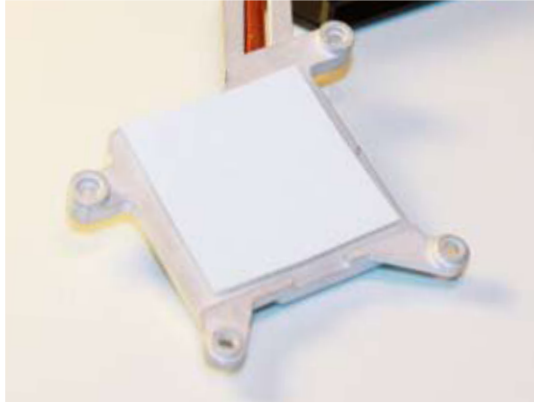
TG-X provides good compliance and softness.

Property	TG-X	Unit	Tolerance	Test Method
Colour	Grey	-	-	Visual
Thickness (Available thickness range)	0.5 / 1.0	mm	-	ASTM D374
	0.0197~0.0394	inch	-	ASTM D374
Thermal Conductivity	12	W/m.k	-	ASTM D5470
Flame Rating	V-0	-	-	UL 94
Dielectric Breakdown Voltage	12	kV/mm	-	ASTM D149
Weight Loss	<1	%	-	ASTM E595
Specific Gravity	3.4	g/cm³	±0.2	ASTM D792
Working Temperature	-45~ +200	°C	-	-
Volume Resistance	>10 ¹¹	Ohm-cm	-	ASTM D257
Standard Shape	-	Sheet ones	-	-
Hardness	60	Shore 00	±5	ASTM D2240

Available with an adhesive backing



Ultra Soft Thermal Conductive Pad



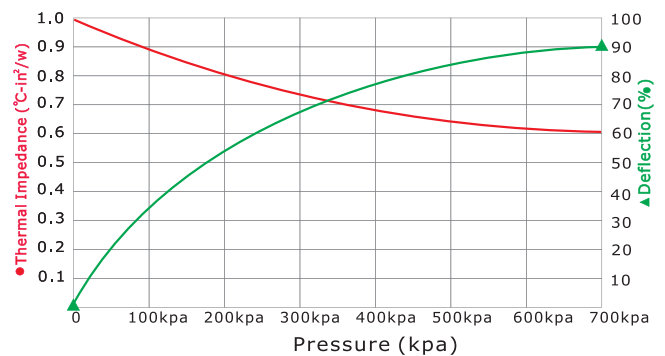
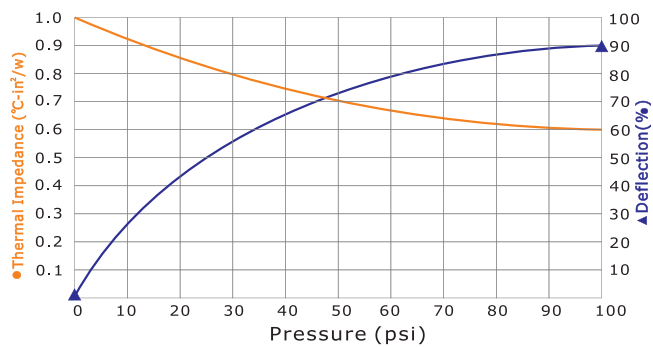
Features

Superior thermal conductivity
Highly compressible
Naturally tacky
Low Shore OO hardness
Low oil bleed
Electrically insulating

Applications

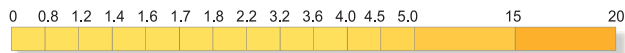
Electronic components: IC - CPU - MOS
LED - M/B - P/S - Heat Sink
LCD-TV - Notebook PC - PC Telecom Device - Wireless Hub.....etc.
DDR II Module - DVD Applications - Hand-set applications.....etc.

Thermal Resistance V.S Pressure V.S Deflection



Properties

Thermal Conductivity: 2.0 W/m.k
(W / m.k - Z Axis)



Testing sample thickness : 1.0 mm

REACH Compliant

ROSH Compliant

Hardness: 30 (Shore 00)
(Shore 00)

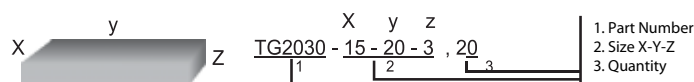


In the thermal resistance vs pressure vs deflection charts TG2030 provides low thermal impedance.

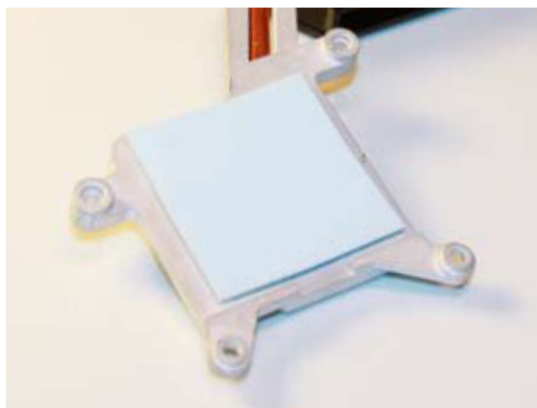
As the pressure increases the thermal impedance decreases. TG2030 provides good compliance and softness.

Property	TG2030	Unit	Tolerance	Test Method
Colour	White	-	-	Visual
Thickness (Available thickness range)	0.5-5.0	mm	-	ASTM D374
	0.0197~0.1969	inch	-	ASTM D374
Thermal Conductivity	2	W/m.k	-	ASTM D5470
Flame Rating	V-0	-	-	UL 94
Dielectric Breakdown Voltage	16	kV/mm	-	ASTM D149
Weight Loss	<1	%	-	ASTM E595
Specific Gravity	2.4	g/cm ³	±0.2	ASTM D792
Working Temperature	-45~ +200	°C	-	-
Volume Resistance	>10 ¹²	Ohm-cm	-	ASTM D257
Elongation	300	%	±13	ASTM D412
Tensile Strength	1	Kgf/cm ²	±2	ASTM D412
Standard Shape	-	Sheet ones	-	-
Hardness	30	Shore 00	±5	ASTM D2240

Available with an adhesive backing



Ultra Soft Thermal Conductive Pad



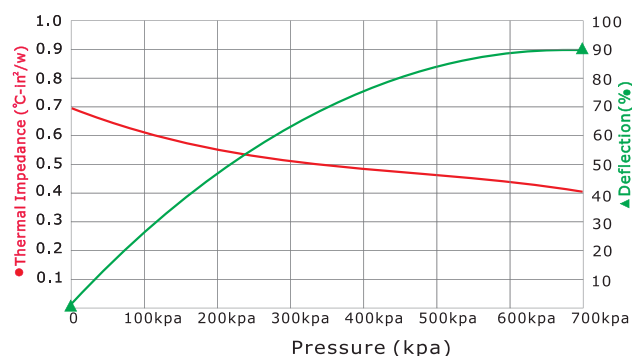
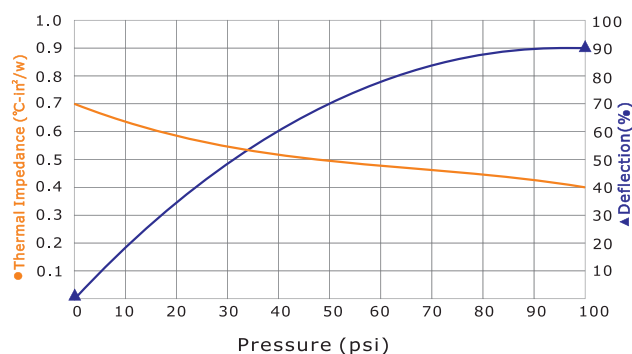
Features

Superior thermal conductivity
Highly compressible
Naturally tacky
Low Shore 00 hardness
Low oil bleed
Electrically insulating

Applications

Electronic components: IC / CPU / MOS
LED / M/B / P/S / Heat Sink / LCD-TV / Notebook PC / PC / Telecom Device /
Wireless Hub etc....
DDR II Module / DVD Applications / Hand-Set applications etc...

Thermal Resistance V.S Pressure V.S Deflection



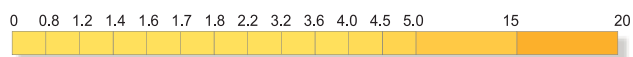
Properties

Thermal Conductivity: 4.0 W/m.k
(W / m.k - Z Axis)

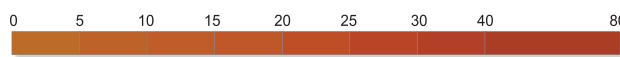
REACH Compliant

RoHS Compliant

Hardness: 40 (Shore 00)
(Shore 00)



Testing sample thickness : 1.0 mm



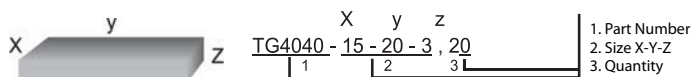
In the thermal resistance vs pressure vs deflection charts TG4040 provides low thermal impedance.

As the pressure increases the thermal impedance decreases.

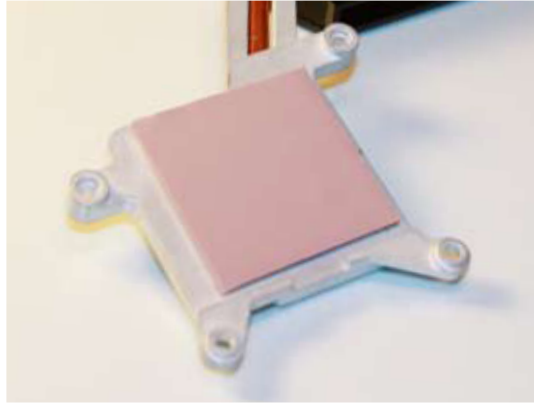
TG4040 provides good compliance and softness.

Property	TG4040	Unit	Tolerance	Test Method
Colour	Blue	-	-	Visual
Thickness (Available thickness range)	0.5-5.0	mm	-	ASTM D374
	0.0197~0.1969	inch	-	ASTM D374
Thermal Conductivity	4	W/m.k	-	ASTM D5470
Flame Rating	V-0	-	-	UL 94
Dielectric Breakdown Voltage	15	kV/mm	-	ASTM D149
Weight Loss	<1	%	-	ASTM E595
Specific Gravity	2.8	g/cm ³	±0.2	ASTM D792
Working Temperature	-45~ +200	°C	-	-
Volume Resistance	>10 ¹²	Ohm-cm	-	ASTM D257
Elongation	100	%	±13	ASTM D412
Tensile Strength	1	Kgf/cm ²	±2	ASTM D412
Standard Shape	-	Sheet ones	-	-
Hardness	40	Shore 00	±5	ASTM D2240

Available with an adhesive backing



Ultra Soft Thermal Conductive Pad



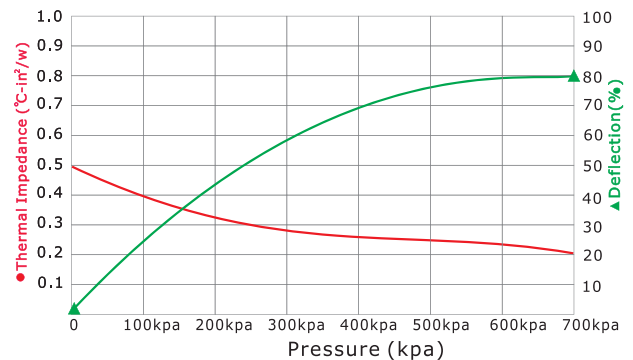
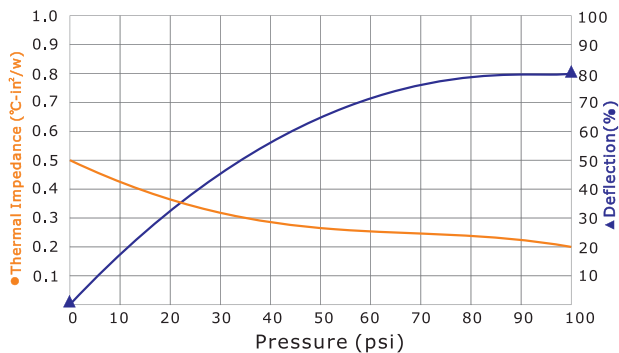
Features

Superior thermal conductivity
Highly compressible
Naturally tacky
Low Shore 00 hardness
Low oil bleed
Electrically insulating

Applications

Electronic components: IC / CPU / MOS
LED / M/B / P/S / Heat Sink / LCD-TV / Notebook PC / PC / Telecom Device /
Wireless Hub etc....
DDR II Module / DVD Applications / Hand-Set applications etc...

Thermal Resistance V.S Pressure V.S Deflection



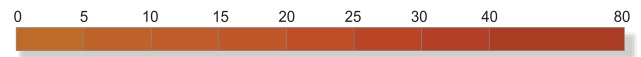
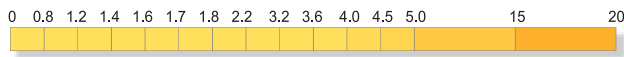
Properties

REACH Compliant

RoHS Compliant

Thermal Conductivity: 6.0 W/m.k
(W / m.k - Z Axis)

Hardness: 50 (Shore 00)
(Shore 00)



Testing sample thickness : 1.0 mm

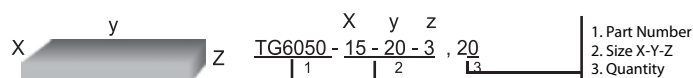
In the thermal resistance vs pressure vs deflection charts TG6050 provides low thermal impedance.

As the pressure increases the thermal impedance decreases.

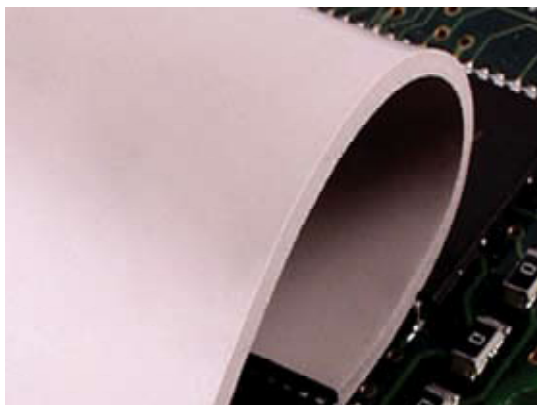
TG6050 provides good compliance and softness.

Property	TG6050	Unit	Tolerance	Test Method
Colour	Red	-	-	Visual
Thickness (Available thickness range)	0.5-2.0	mm	-	ASTM D374
	0.0197~0.0787	inch	-	ASTM D374
Thermal Conductivity	6	W/m.k	-	ASTM D5470
Flame Rating	V-0	-	-	UL 94
Dielectric Breakdown Voltage	13	kV/mm	-	ASTM D149
Weight Loss	<1	%	-	ASTM E595
Specific Gravity	3.2	g/cm ³	±0.2	ASTM D792
Working Temperature	-45~ +200	°C	-	-
Volume Resistance	>10 ¹²	Ohm-cm	-	ASTM D257
Elongation	50	%	±13	ASTM D412
Tensile Strength	0.5	Kgf/cm ²	±2	ASTM D412
Standard Shape	-	Sheet ones	-	-
Hardness	50	Shore 00	±5	ASTM D2240

Available with an adhesive backing



Thermal Composite Material





Features

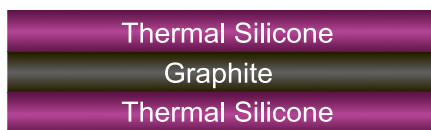
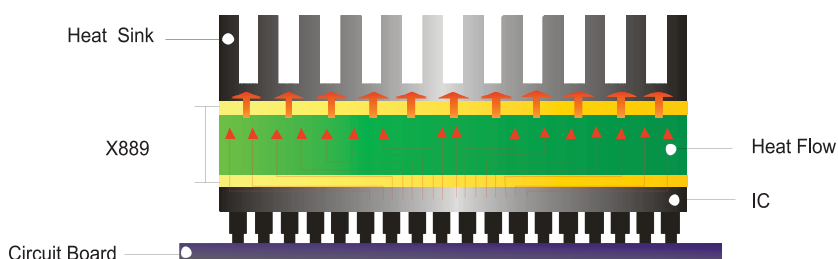
Good heat spreader
Good thermal conductivity
Easy to assemble
High Stability

Applications

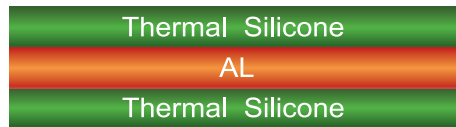
Electronic components: IC / CPU / MOS
LED / M/B / P/S / Heat Sink / LCD-TV / Notebook PC / PC / Telecom Device /
Wireless Hub etc....
DDR II Module / DVD Applications / Hand-Set applications etc...

Properties

-  REACH Compliant
-  RoHS Compliant



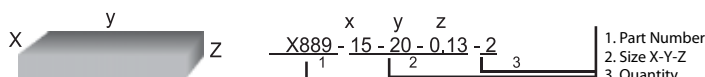
Composition X889



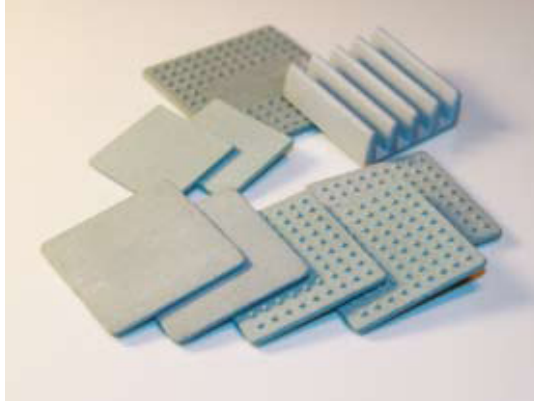
Composition X889-1

Property	X889	X889-1	Unit	Test Method
Colour	Grey	Grey	-	Visual
Thickness (Available thickness range)	0.25~0.6	0.13	mm	ASTM D374
	0.098~0.0236	0.051	inch	ASTM D374
Thermal Conductivity	X, Y, 400	Z, 4	W/m.k	ASTME 1530
	Z, 5			
Flame Rating	V-0	V-0	-	UL 94
Dielectric Breakdown Voltage	>1	>2	kV	ASTM D149
Weight Loss	<1	<1	%	ASTM E595
Specific Gravity	1.85	1.85	g/cm ³	ASTM D792
Working Temperature	-40 ~ +200	-40 ~ +200	°C	-
Volume Resis	2.2 x 10 ¹²	2.2 x 10 ¹²	Ohm-cm	ASTM D257

Available with an adhesive backing



Ceramic Heat Spreader



Features

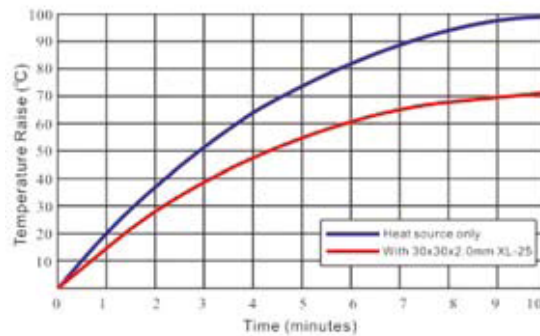
Large contact area
Low weight
High breakdown voltage
Excellent heat spreader
Custom shapes possible

Applications

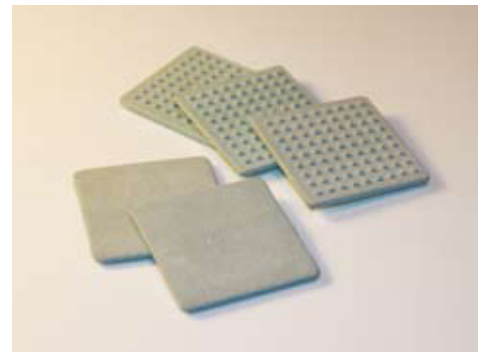
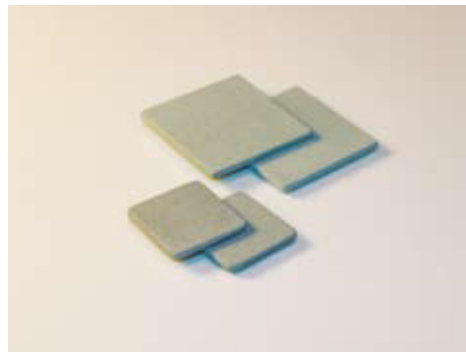
LED / Notebook PC / M/B / Power Transistor / Power Module / CPU / Chip IC

Standard sizes (mm)

1. 10 x 10 x 2.0
2. 20 x 20 x 2.0
3. 30 x 30 x 2.0
4. 40 x 40 x 2.0
5. 40 x 40 x 3.0
6. 40 x 40 x 3.0
7. 50 x 50 x 3.0



Used examples: Heat sources with XL-25



Property	XL-25	Unit	Test Method
Colour	Grey	-	Visual
Thermal Conductivity	6.79	W/m.k	-
Dielectric Breakdown Voltage	>500	Voltage	ASTM D149
Specific Gravity	1.89	g/cm ³	CNS 619
Surface Resistance	>10 ⁹	Ohm	ASTMD 257
Flexural Strength	47.5	Kgf/cm ²	CNS 12701
Porosity	30	%	CNS 619
Working Temperature	>500	°C	-
Linear Temperature Expansion Coefficient	4.13	10/06/11	RT~300 °C
Main Composition	SiC / Al ₂ O ₃ / SiO ₂	-	-
Hardness	5~6	Moh's	DIN EN101-1992

Thermal Conductive Gel

Features

Good thermal conductivity
Water proof
Easy to mix

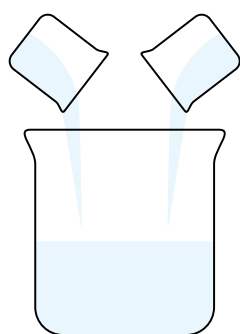
Applications

Electronic components: IC / CPU / MOS
LED / M/B / P/S / Heat Sink / LCD-TV / Notebook PC / PC / Telecom Device /
Wireless Hub etc....
DDR II Module / DVD Applications / Hand-Set applications etc...

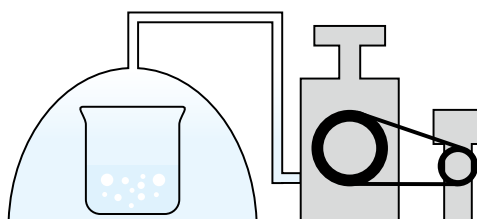
Storage

S720 AB has a shelf-life of twelve (12) months from the date of manufacture, as indicated by the lot number, when stored in the original unopened packaging, contained at or below 25 °C.

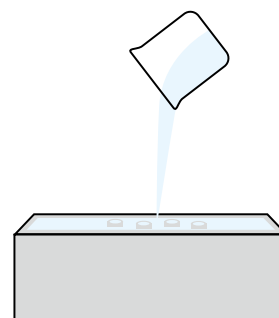
Procedure



1. Mix




2. Vacuum out air

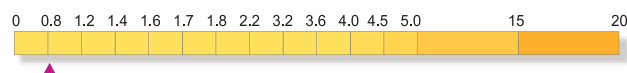


3. Pour S720AB

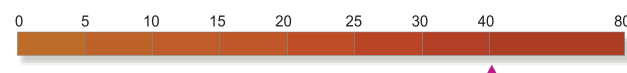
Properties

-  REACH Compliant
-  ROHS Compliant

Thermal Conductivity: 0.8 W/m.k
(W / m.k - Z Axis)



Hardness: 40-50 (Shore A)
(Shore A)



Property	S720AB	Unit	Tolerance	Test Method
Colour	White	-	-	Visual
Thermal Conductivity	0.8	W/m.k	-	ASTM D5470
Dielectric Breakdown Voltage	>6	kV	-	ASTM D149
Weight Loss	<1	%	-	ASTM E595
Specific Gravity	1.97	g/cm ³	±0.2	ASTM D792
Working Temperature	-40~ 180	°C	-	-
Viscosity	2000-3000	cps	-	ASTM D412
Standard package	1KG	pot	-	-
Hardness	40-50	Shore A	±5	ASTM D2240

S720AB - 20gram
1 2

1. Part Number
2. Quantity

Thermal Conductive Gel

Features

Epoxy based
High thermal conductivity
Cure at room temperature or elevated temperature
Water proof



Applications

Electronic components: IC / CPU / MOS
LED / M/B / P/S / Heat Sink / LCD-TV / Notebook PC / PC / Telecom Device /
Wireless Hub etc....
DDR II Module / DVD Applications / Hand-Set applications etc....

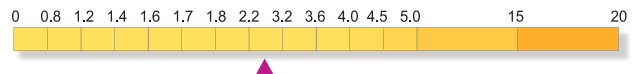
Storage

A96AB has a shelf-life of twelve (12) months from the date of manufacture, as indicated by the lot number, when stored in the original, unopened container, stored at or below 25°C

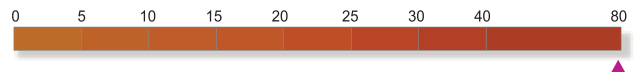
Properties

-  REACH Compliant
-  ROHS Compliant

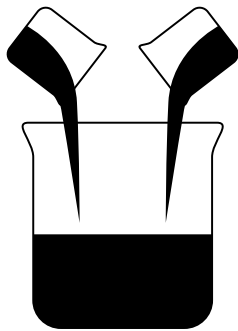
Thermal Conductivity: 2.5 W/m.k
(W/m.k - Z Axis)



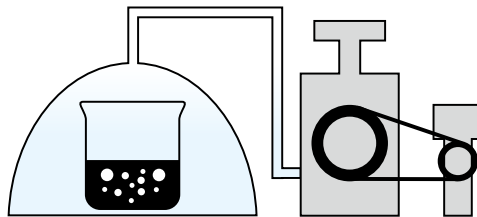
Hardness: 80 (Shore A)
(Shore A)



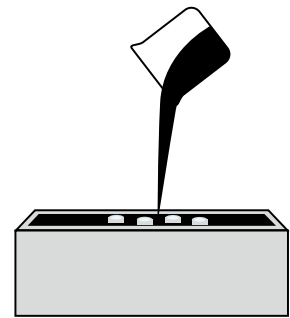
Procedure



1. Mix



2. Vacuum out air



3. Pour A96AB

Property	A96AB	Unit	Tolerance	Test Method
Colour	White	-	-	Visual
Thermal Conductivity	25	W/m.k	-	ASTM D5470
Dielectric Breakdown Voltage	>10	kV	-	ASTM D149
Weight Loss	<1	%	-	ASTM E595
Specific Gravity	1.8	g/cm ³	±0.2	ASTM D792
Working Temperature	-25 ~ 150	°C	-	-
Viscosity	1800 - 2500	cps	-	ASTM D412
Standard Package	1kg	pot	-	-
Hardness	80	Shore A	±5	ASTM D2240

A96AB - 20gram
1 2

1. Part Number
2. Quantity



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